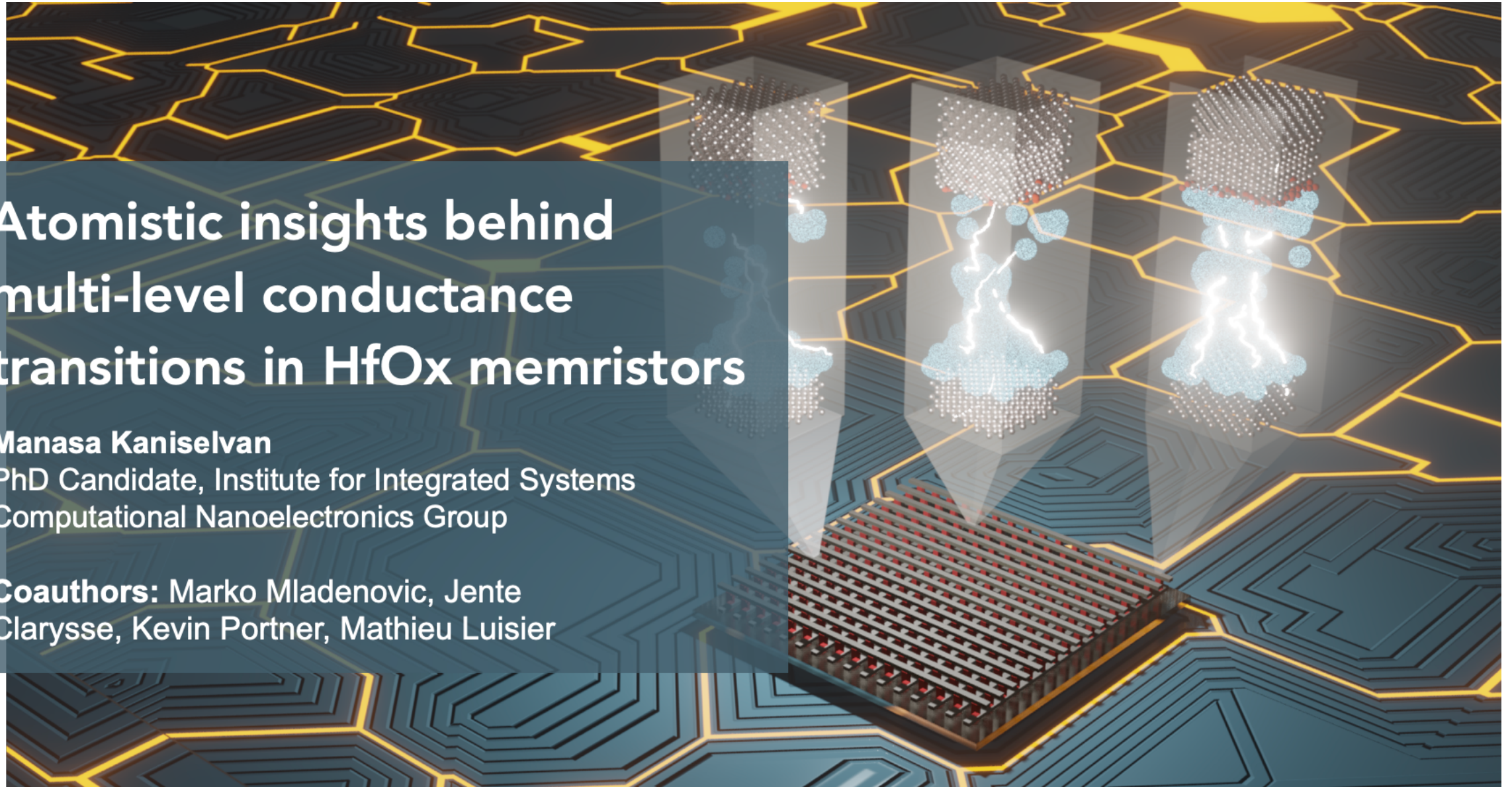


Atomistic insights behind multi-level conductance transitions in HfOx memristors

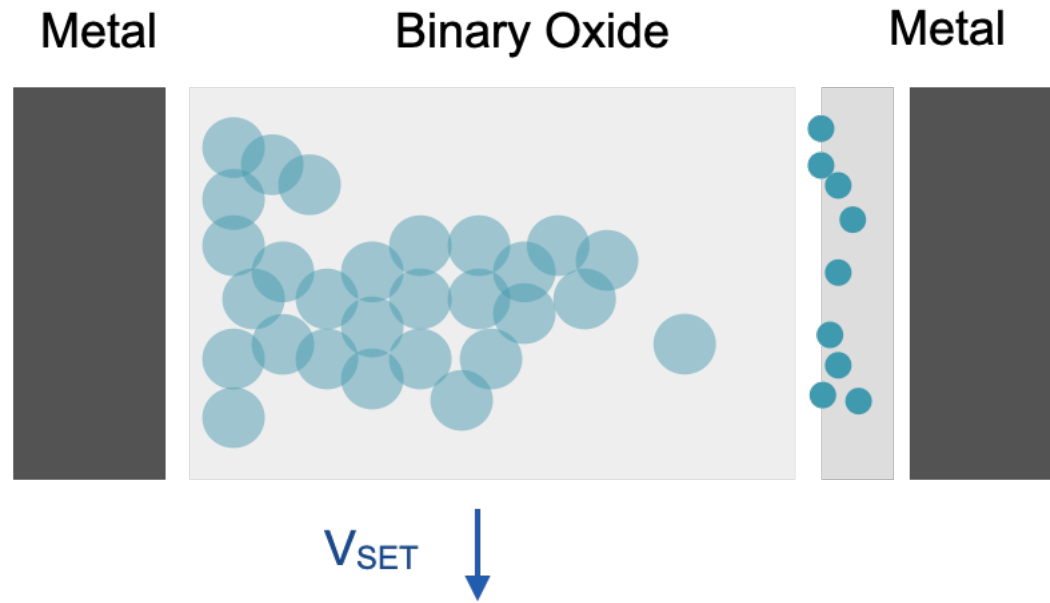
Manasa Kaniselvan

PhD Candidate, Institute for Integrated Systems
Computational Nanoelectronics Group

Coauthors: Marko Mladenovic, Jente Clarysse, Kevin Portner, Mathieu Luisier

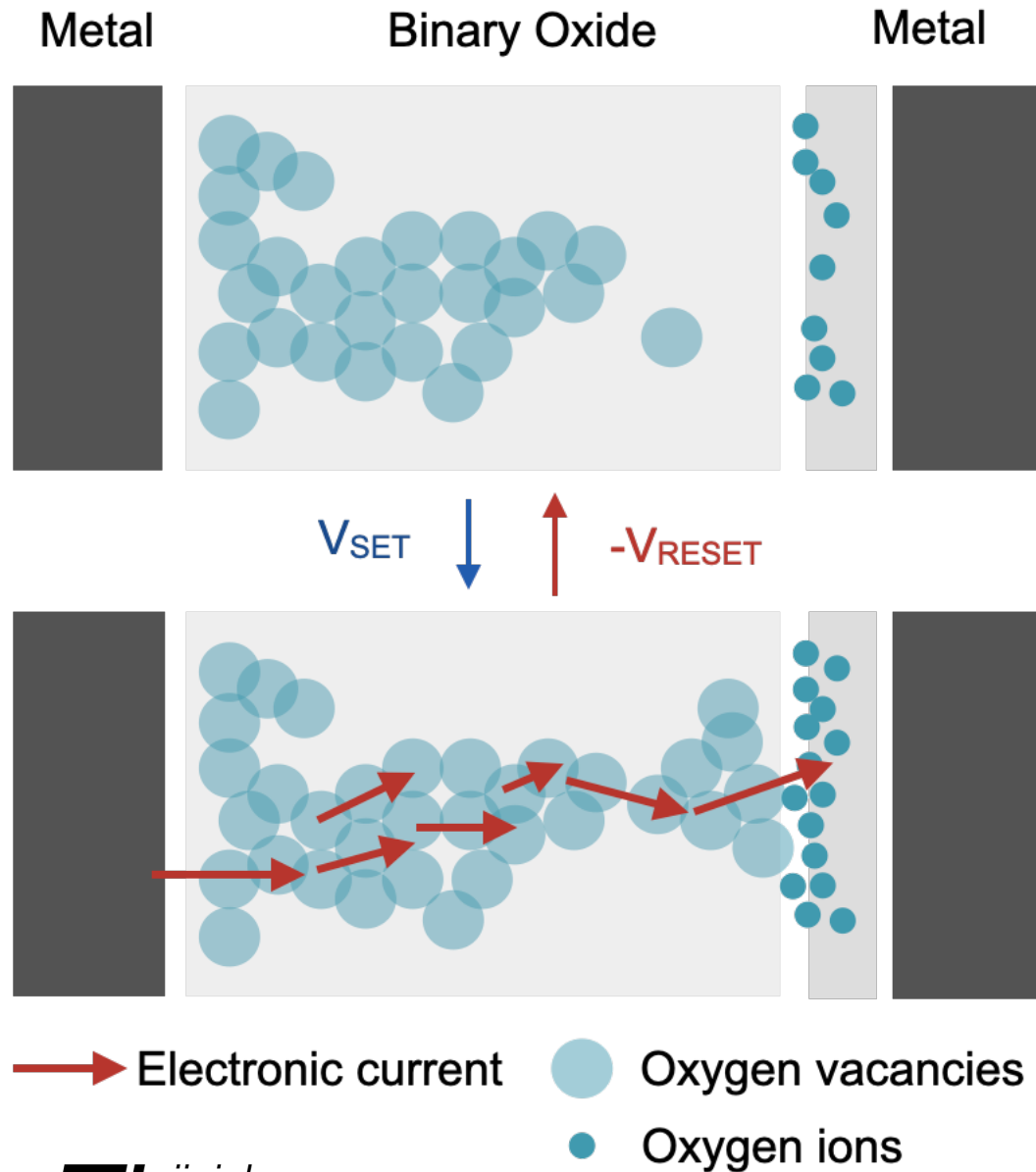


Oxide-based RRAM

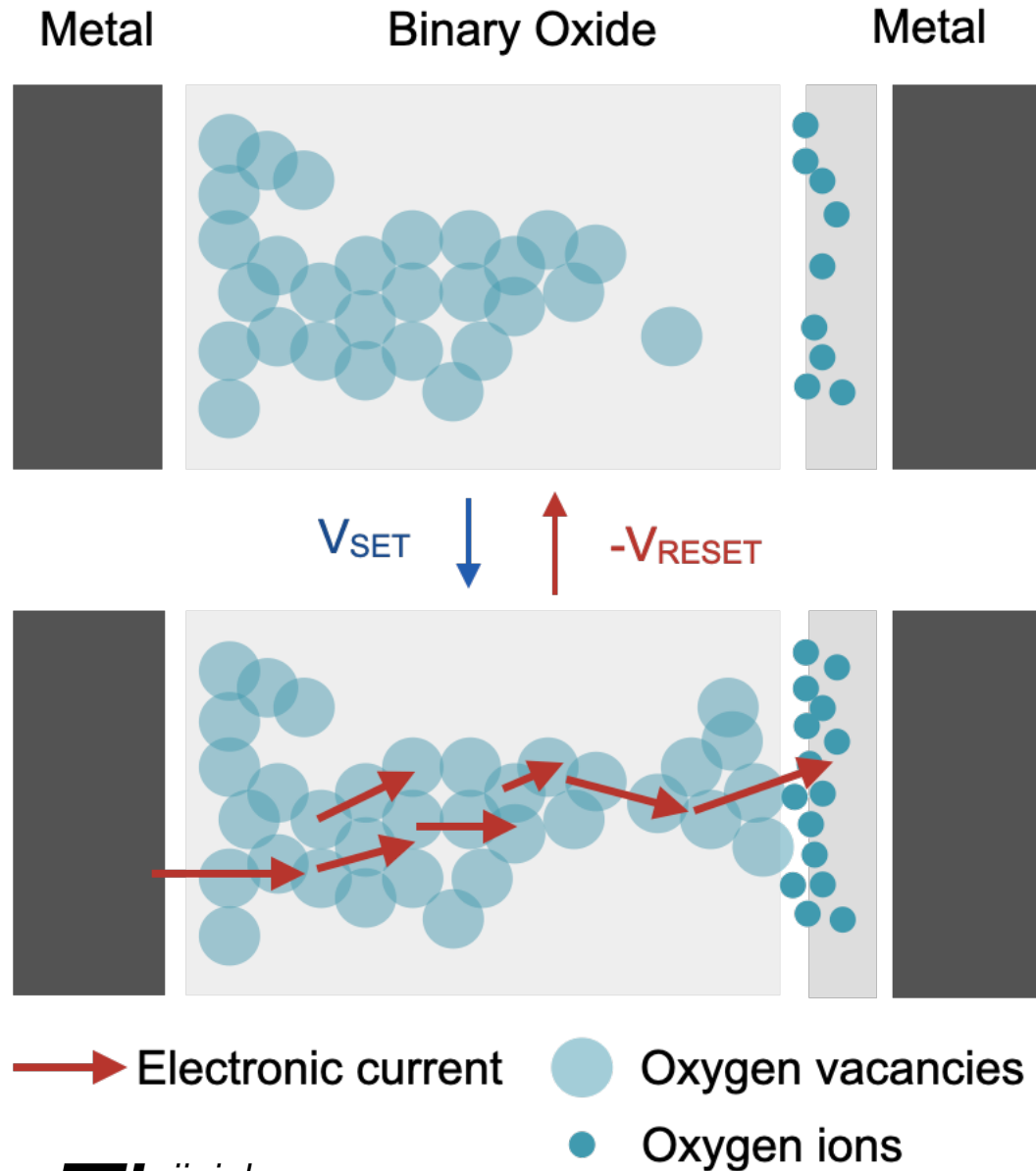


- Oxygen vacancies
- Oxygen ions

Oxide-based RRAM



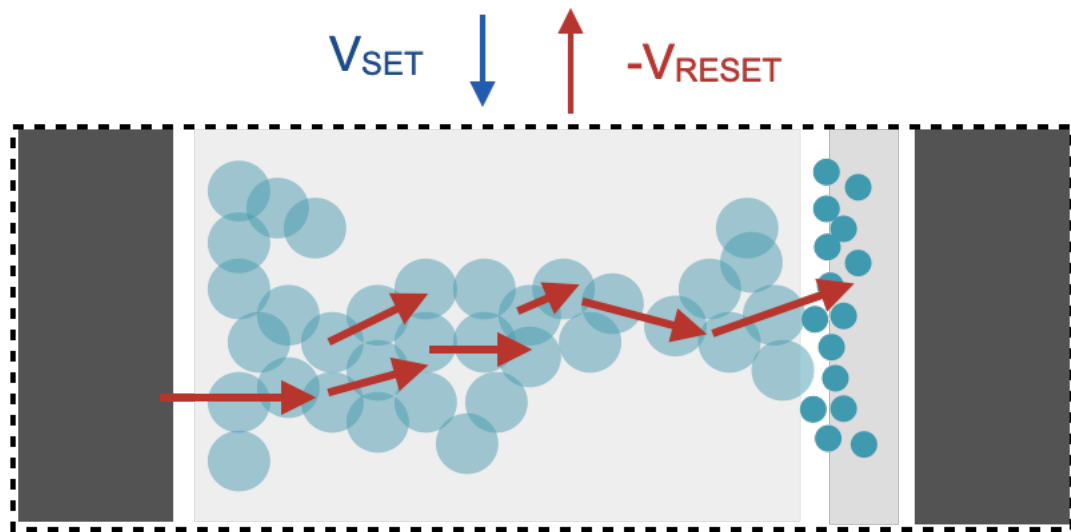
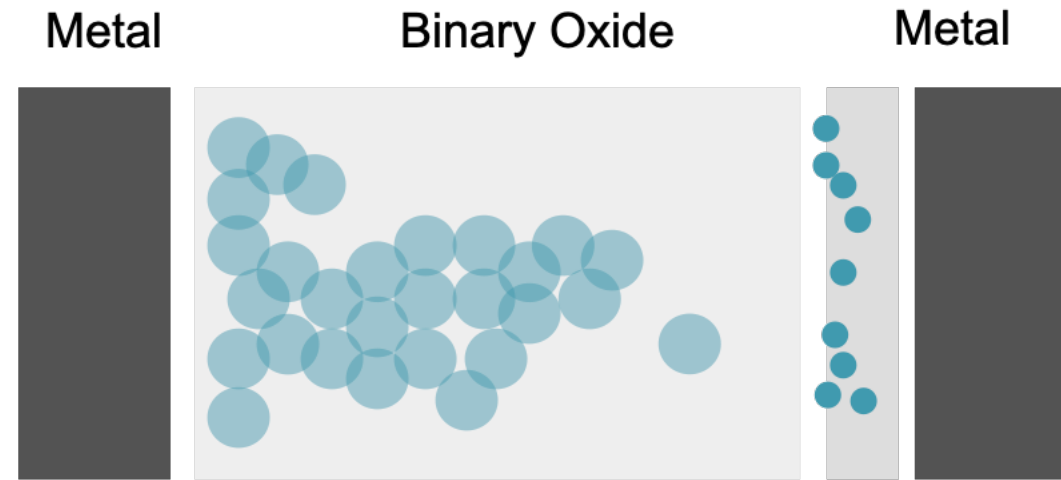
Oxide-based RRAM



Emerging applications of these devices

- Storage, on-chip memory (digital)
- Synaptic weights (analog)

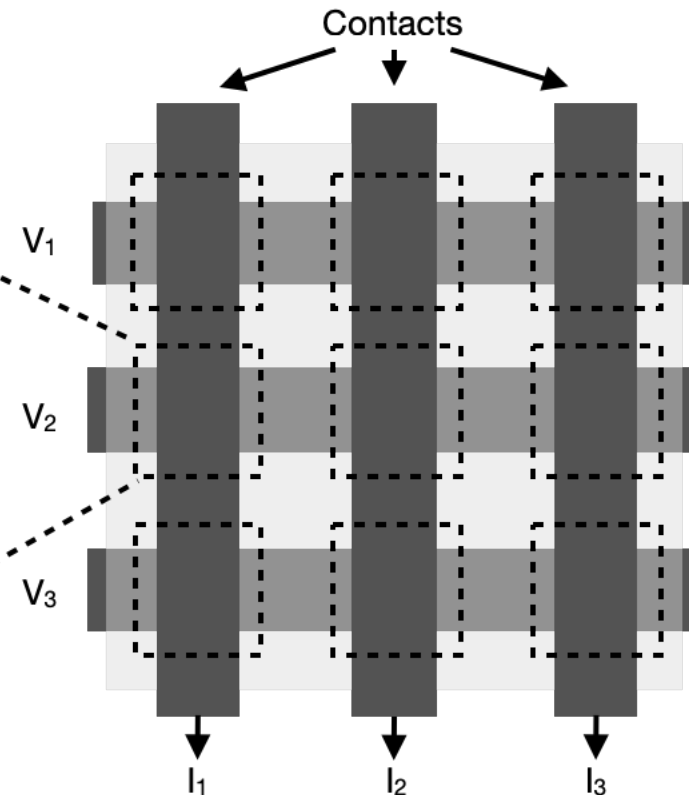
Oxide-based RRAM



→ Electronic current ● Oxygen vacancies
● Oxygen ions

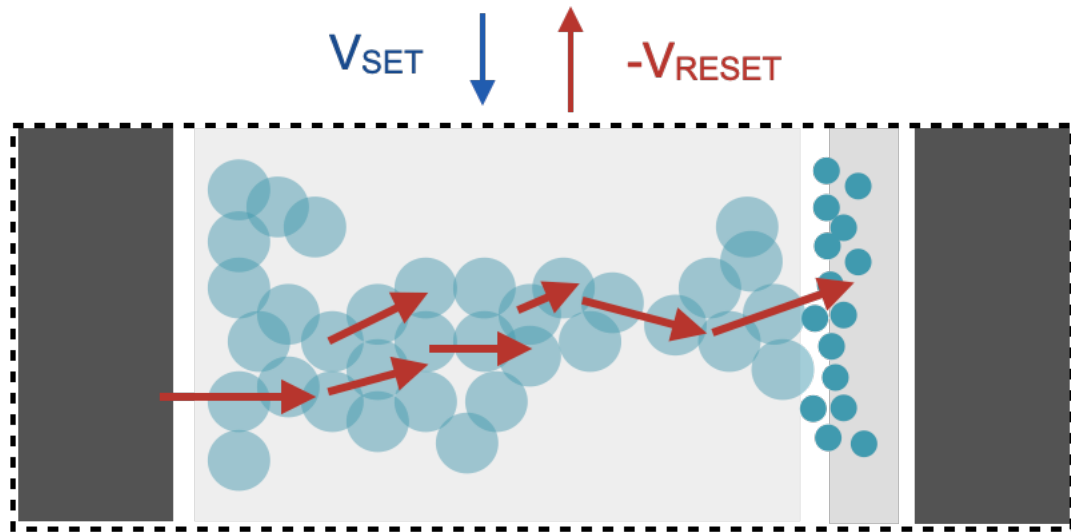
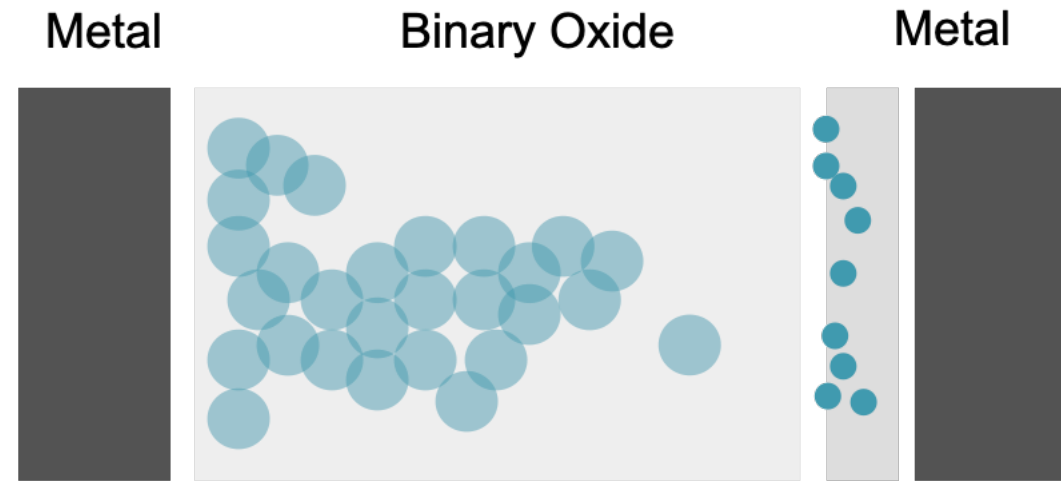
Emerging applications of these devices

- **Storage, on-chip memory (digital)**
- **Synaptic weights (analog)**



$$I_i = \sum_{j=1}^N \frac{V_j}{R_{ji}}$$

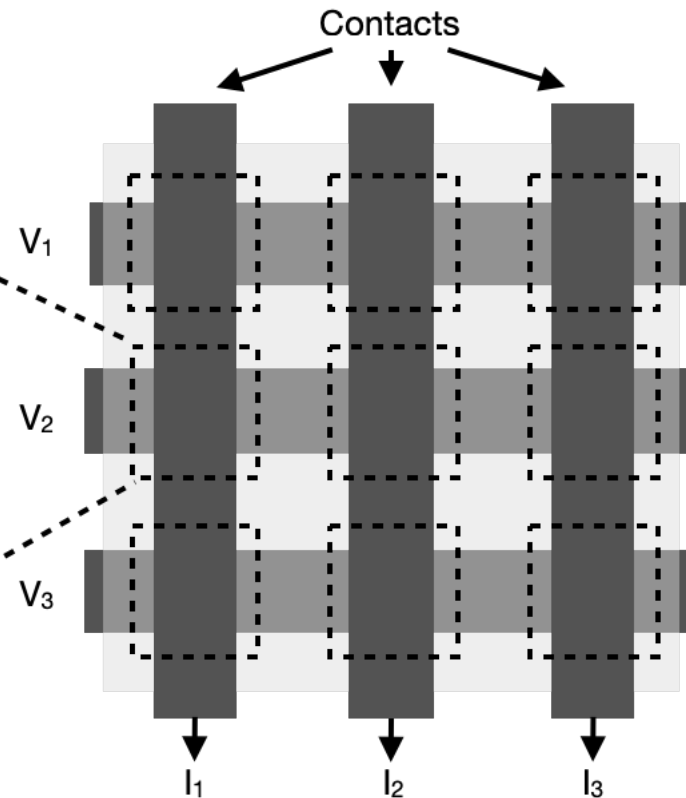
Oxide-based RRAM



→ Electronic current ● Oxygen vacancies
● Oxygen ions

Emerging applications of these devices

- **Storage, on-chip memory (digital)**
- Synaptic weights (analog)

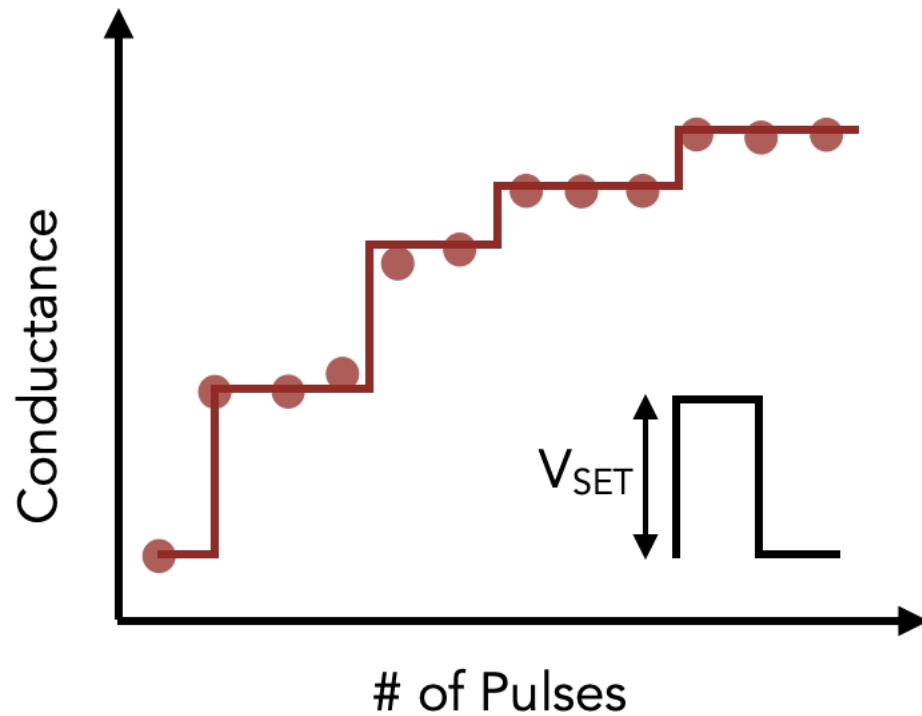


$$I_i = \sum_{j=1}^N \frac{V_j}{R_{ji}}$$

Tunable

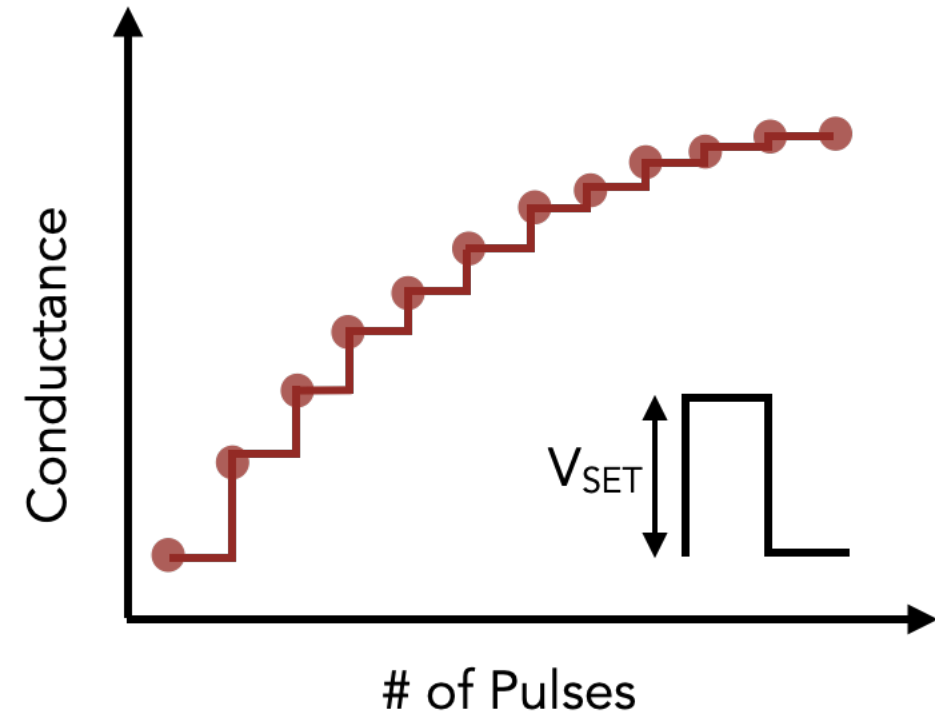
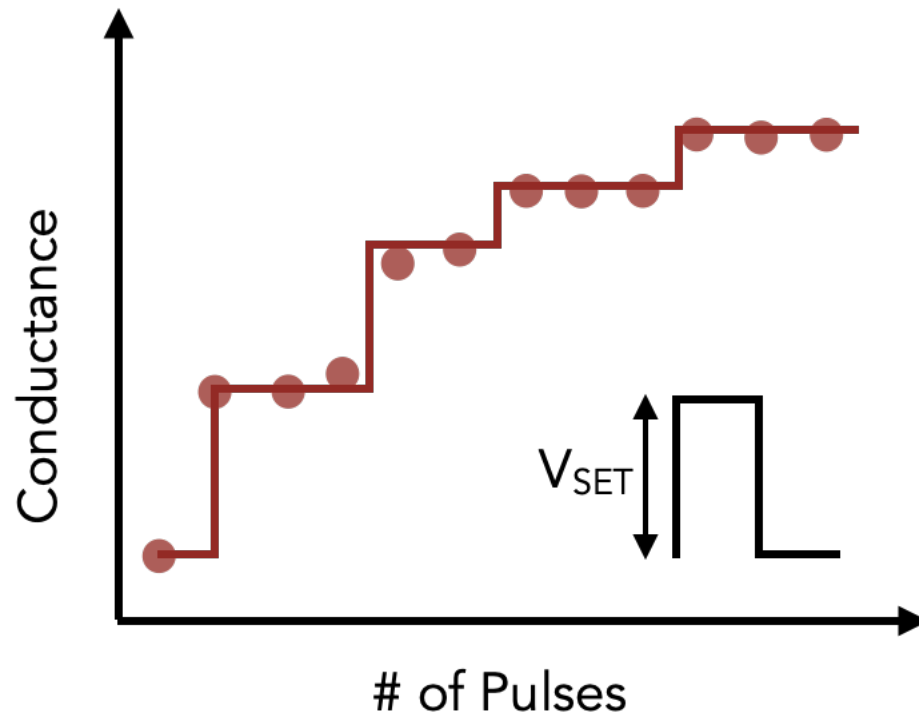
Challenges behind Designing Analog RRAM

- Increase the number of achievable conductances/synaptic weights



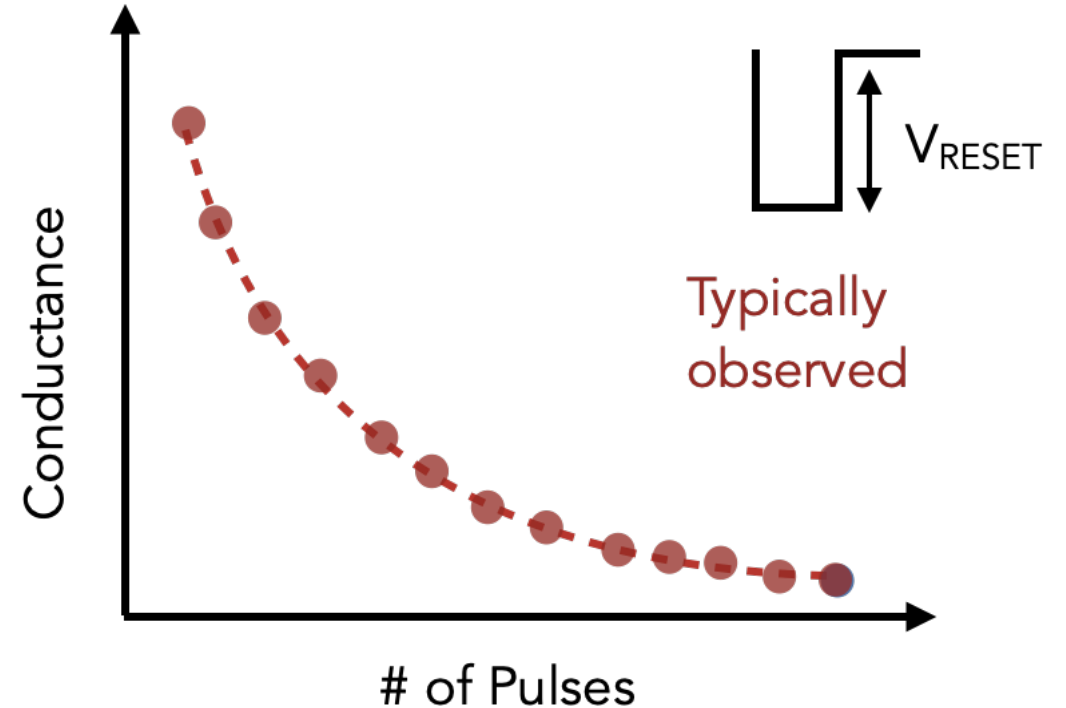
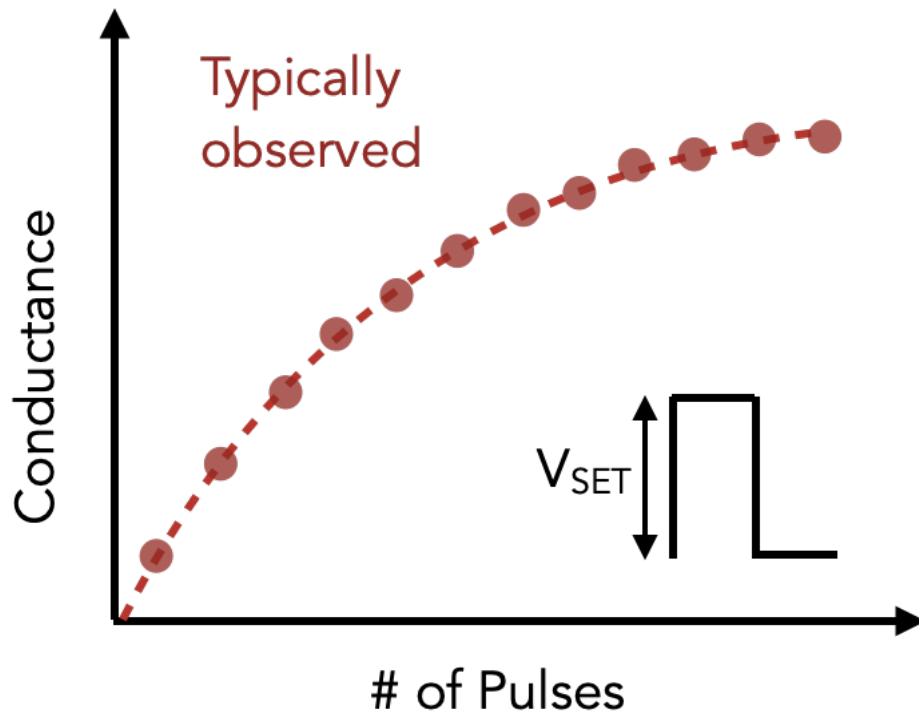
Challenges behind Designing Analog RRAM

- Increase the number of achievable conductances/synaptic weights



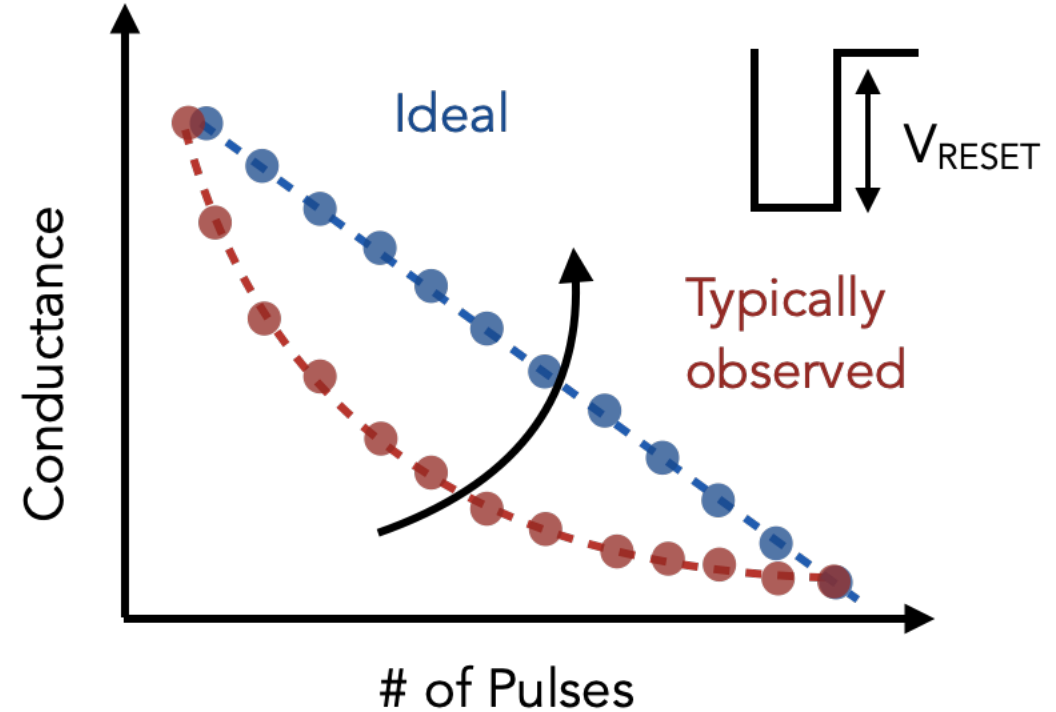
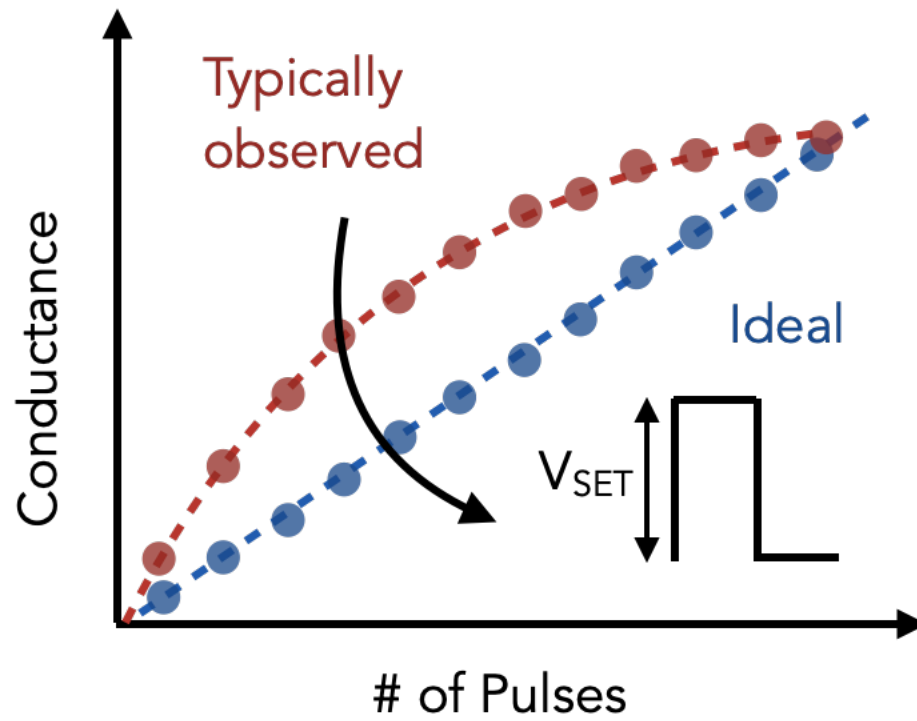
Challenges behind Designing Analog RRAM

- Increase the number of achievable conductances/synaptic weights
- Linearize the transitions between these conductances/weights

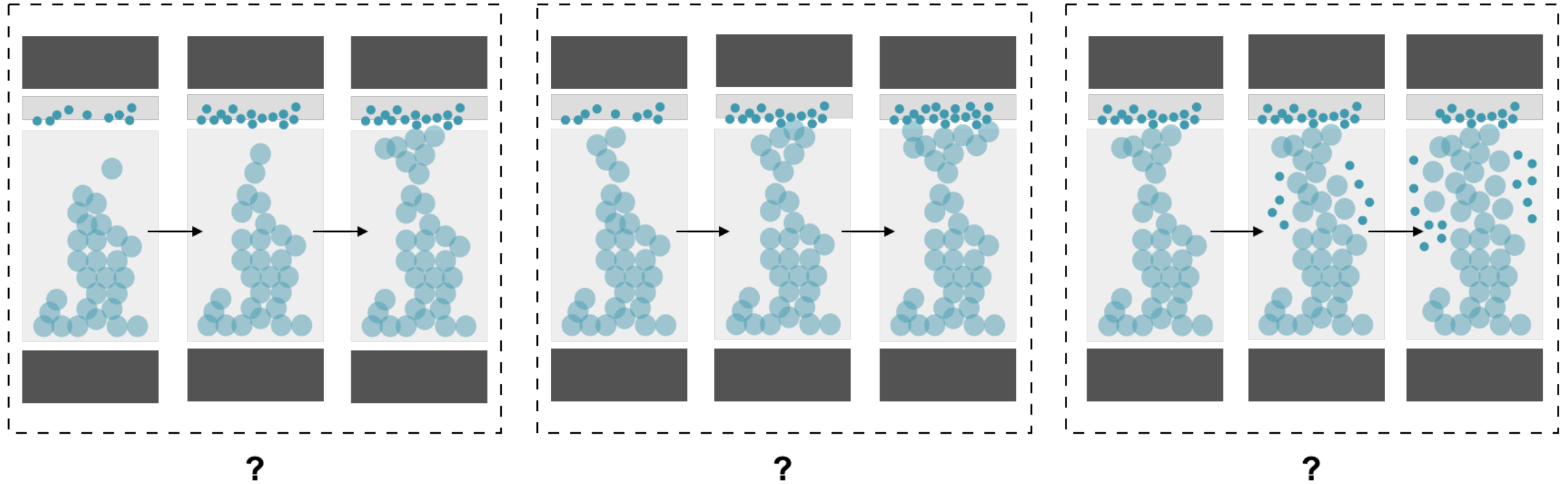


Challenges behind Designing Analog RRAM

- Increase the number of achievable conductances/synaptic weights
- Linearize the transitions between these conductances/weights



Switching Mechanisms for Intermediate States



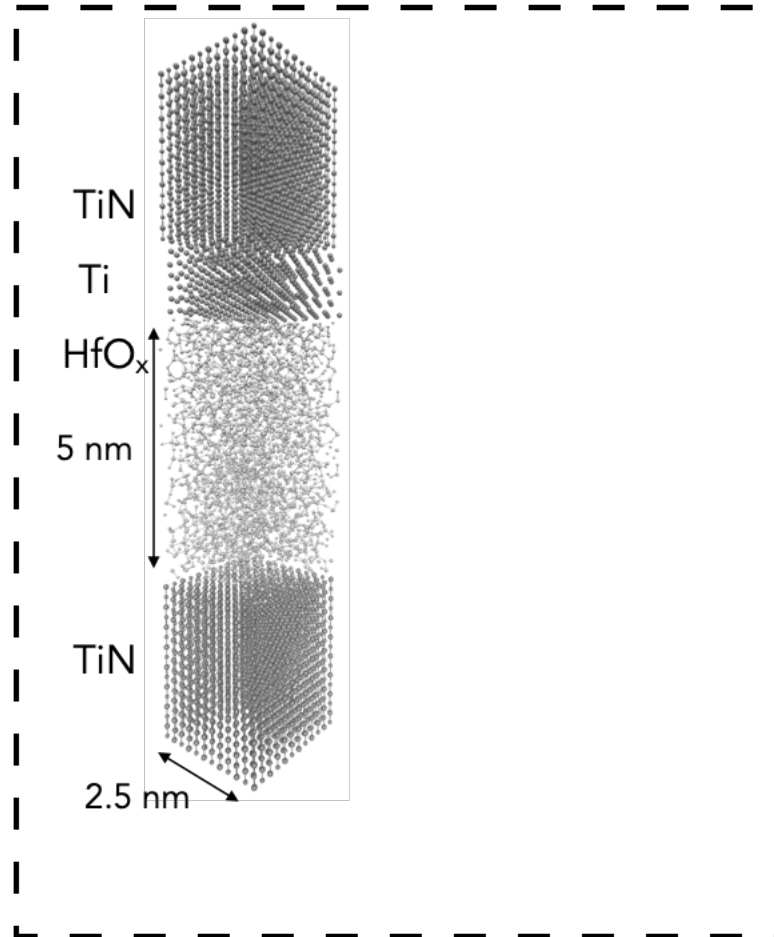
- Oxygen vacancies
- Oxygen ions

- Investigate the **ionic kinetics** and **electronic current flow** behind analog device behaviour with **ab-initio** and **atomistic simulations**

- Investigate the **ionic kinetics** and **electronic current flow** behind analog device behaviour with **ab-initio** and **atomistic simulations**
- Provide **insight** towards device design

Simulation approach

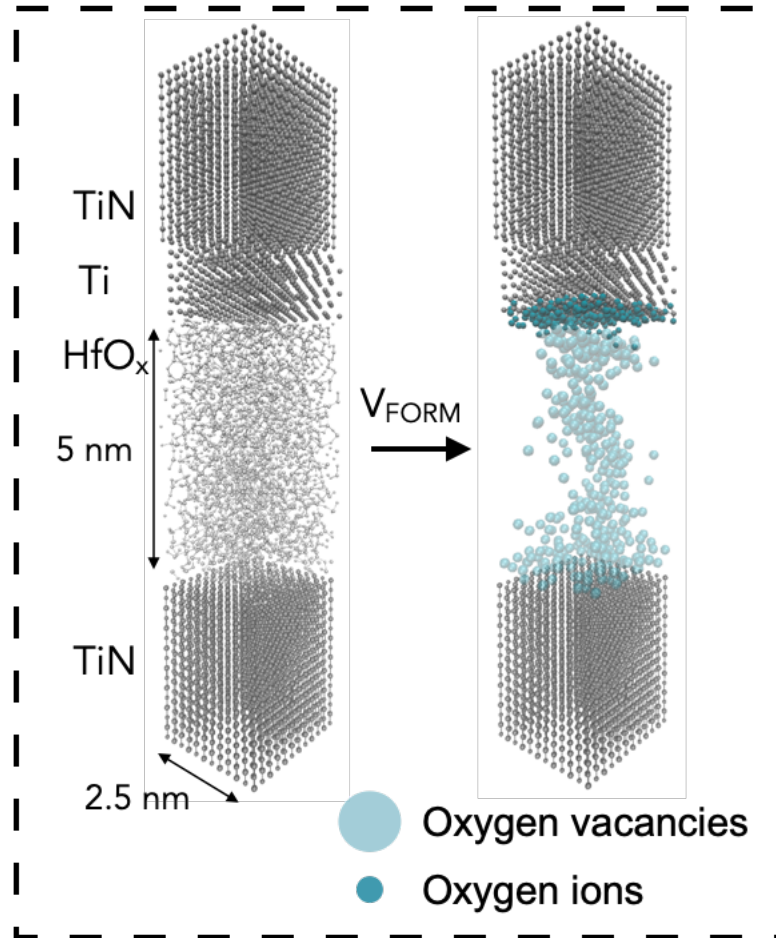
Kinetic Monte Carlo



Atomic Structure

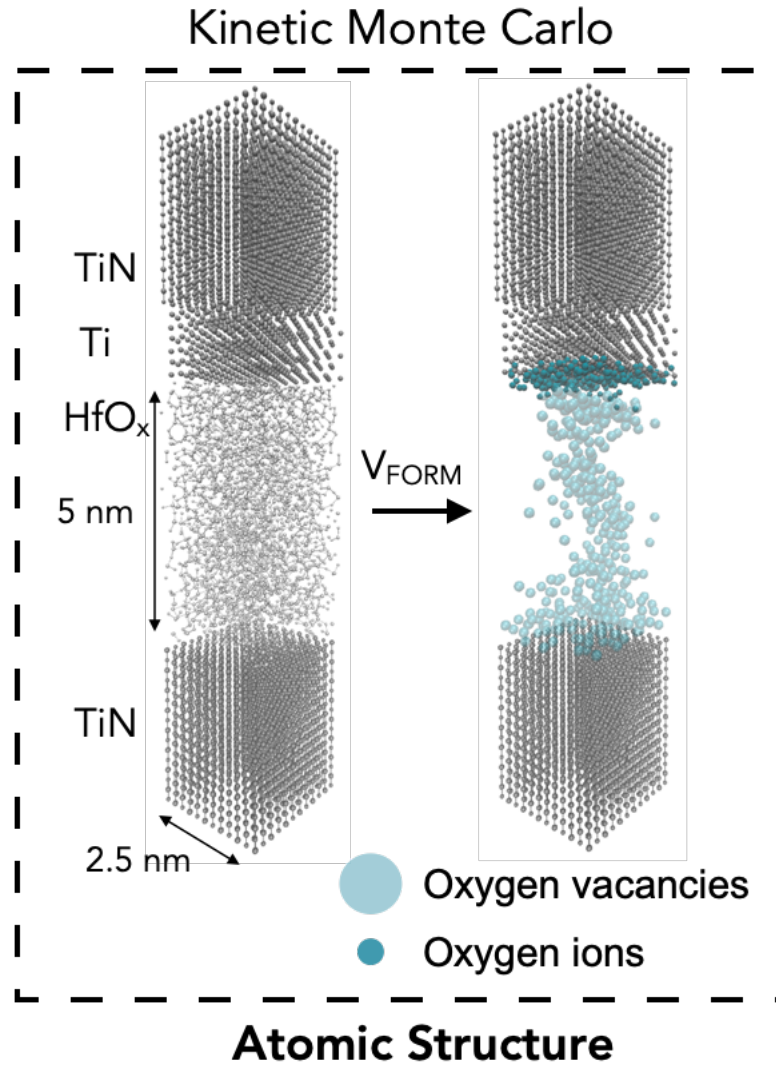
Simulation approach

Kinetic Monte Carlo

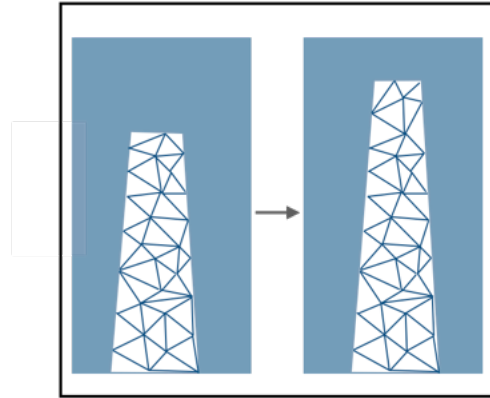


Atomic Structure

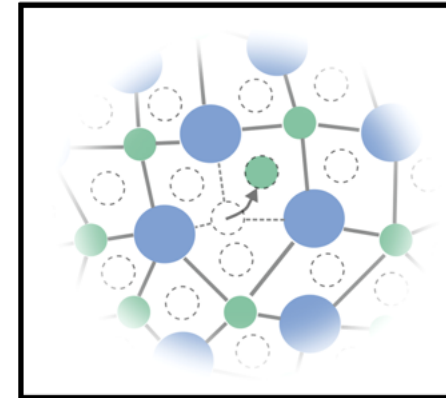
Simulation approach



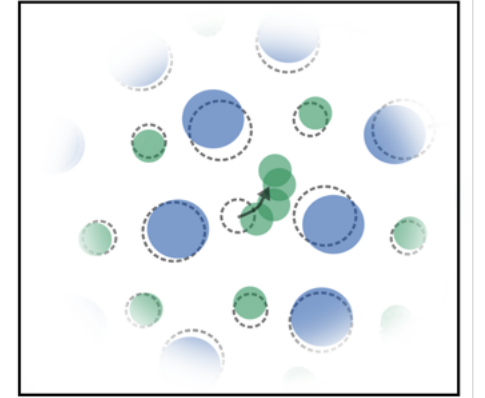
Finite Element



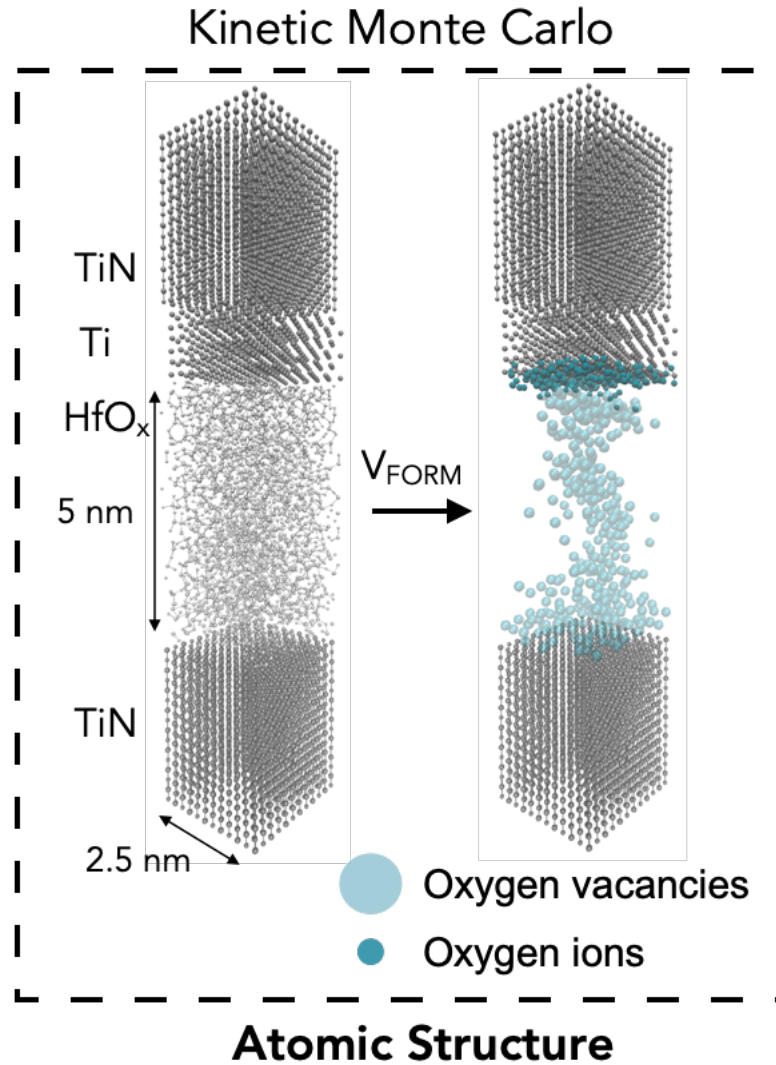
Kinetic Monte Carlo



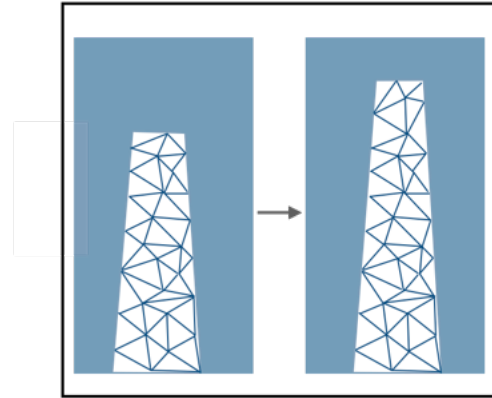
Molecular Dynamics



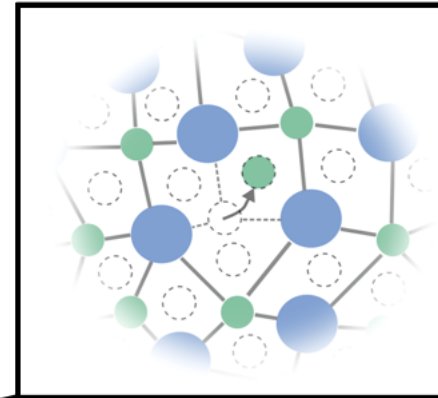
Simulation approach



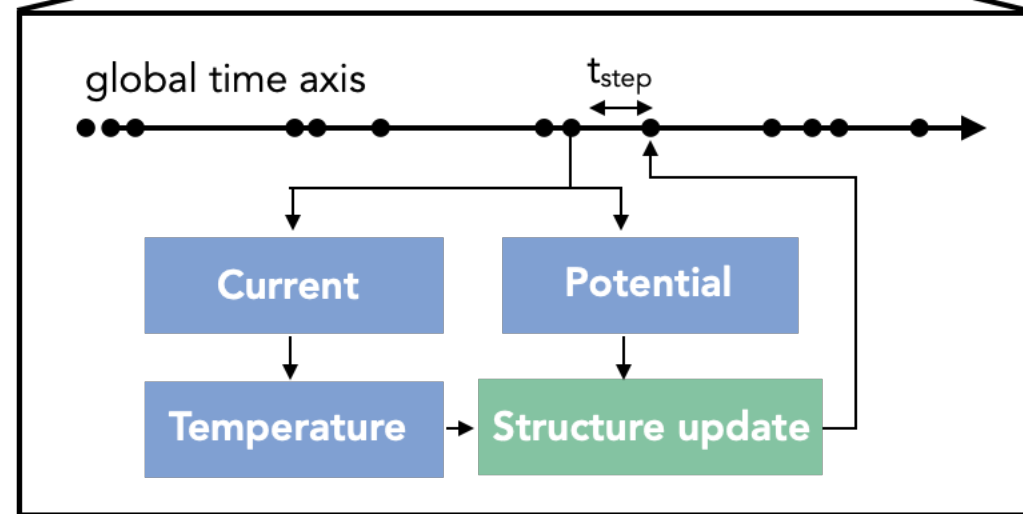
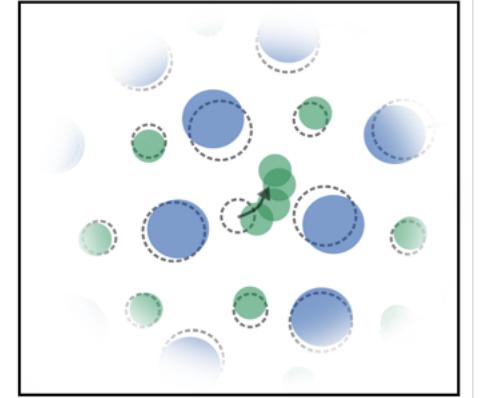
Finite Element



Kinetic Monte Carlo



Molecular Dynamics

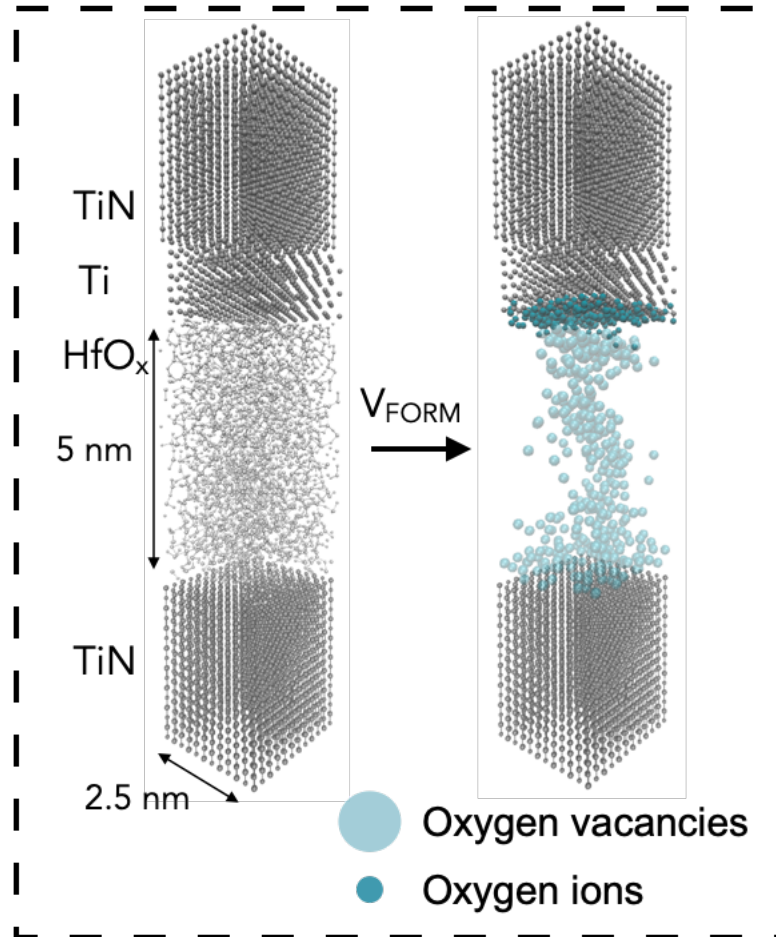


Kaniselvan, M*; Maeder, A*; Mladenović, M; Luisier, M; Ziogas, A.N; "Accelerated Kinetic Monte Carlo Simulations of Atomistically-Resolved Resistive Memory Arrays". (Accepted paper) *International Conference on High Performance Computing, Networking, Storage and Analysis (SC24)* 2024

Kaniselvan, M.; Luisier, M.; Mladenović, M; "An Atomistic Model of Field-Induced Resistive Switching in Valence Change Memory" *ACS Nano* 2023

Simulation approach

Kinetic Monte Carlo



Atomic Structure

Density Functional Theory

H_{cp2k} S_{cp2k}

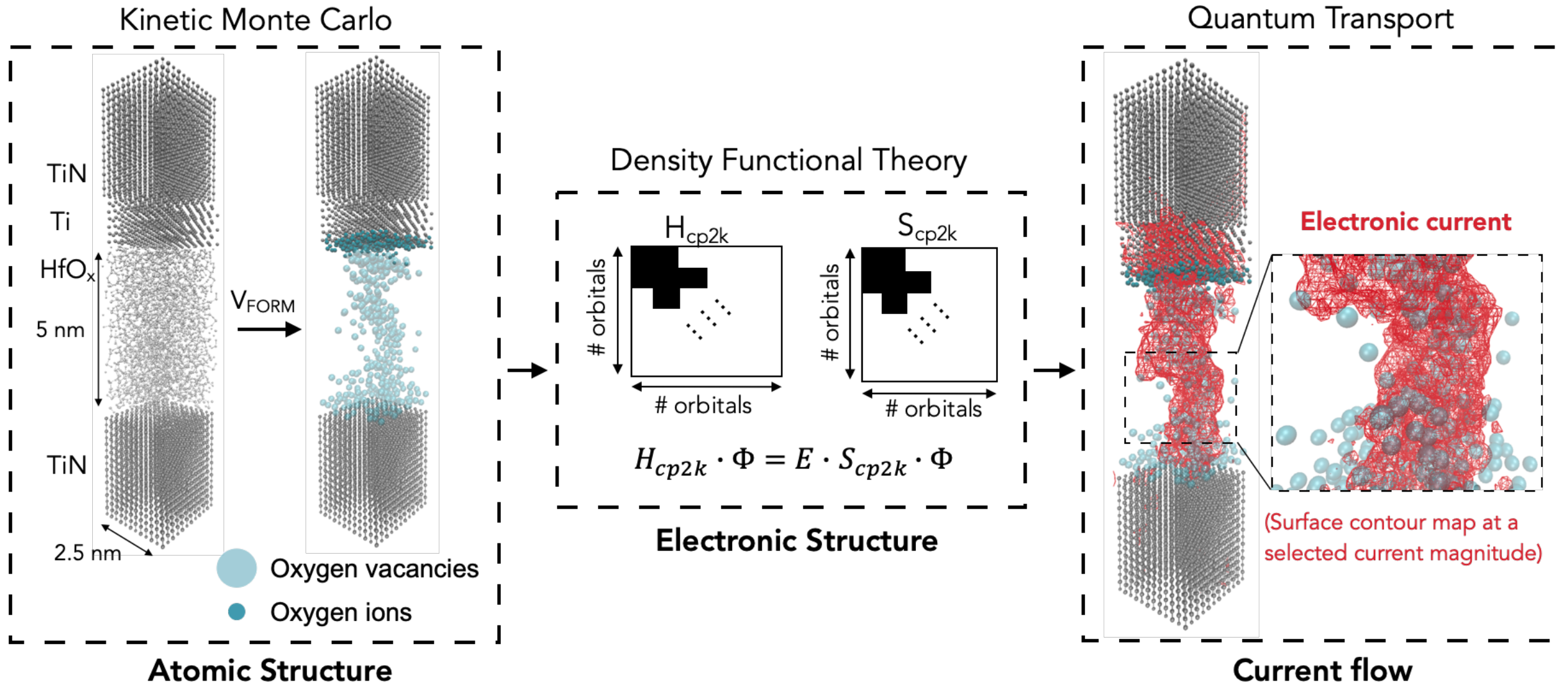
orbitals # orbitals

orbitals # orbitals

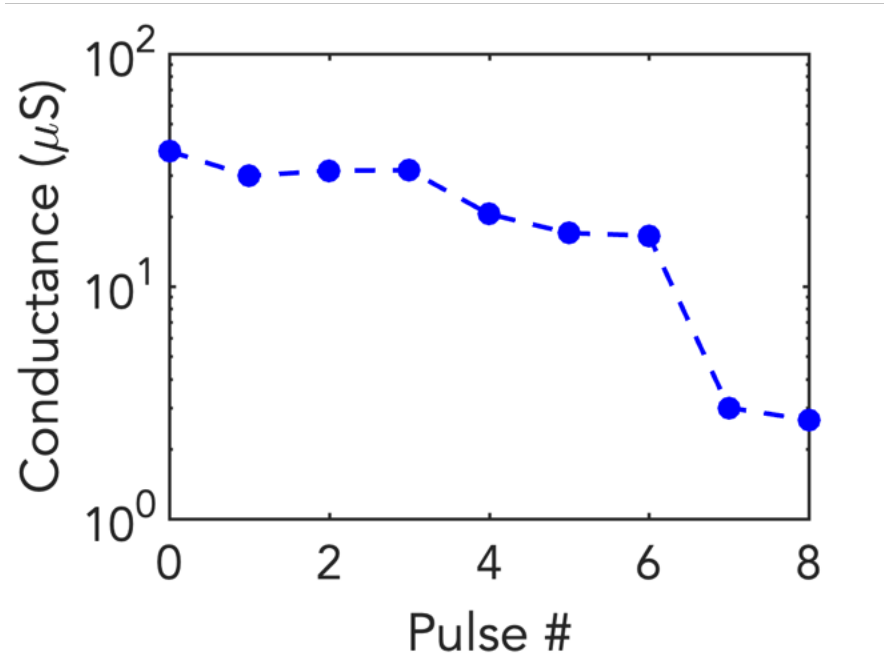
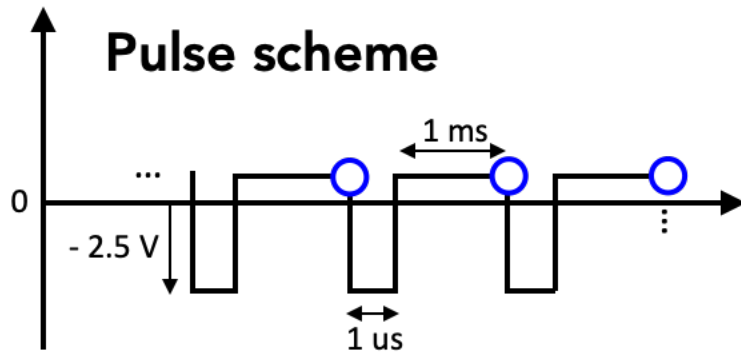
$$H_{\text{cp2k}} \cdot \Phi = E \cdot S_{\text{cp2k}} \cdot \Phi$$

Electronic Structure

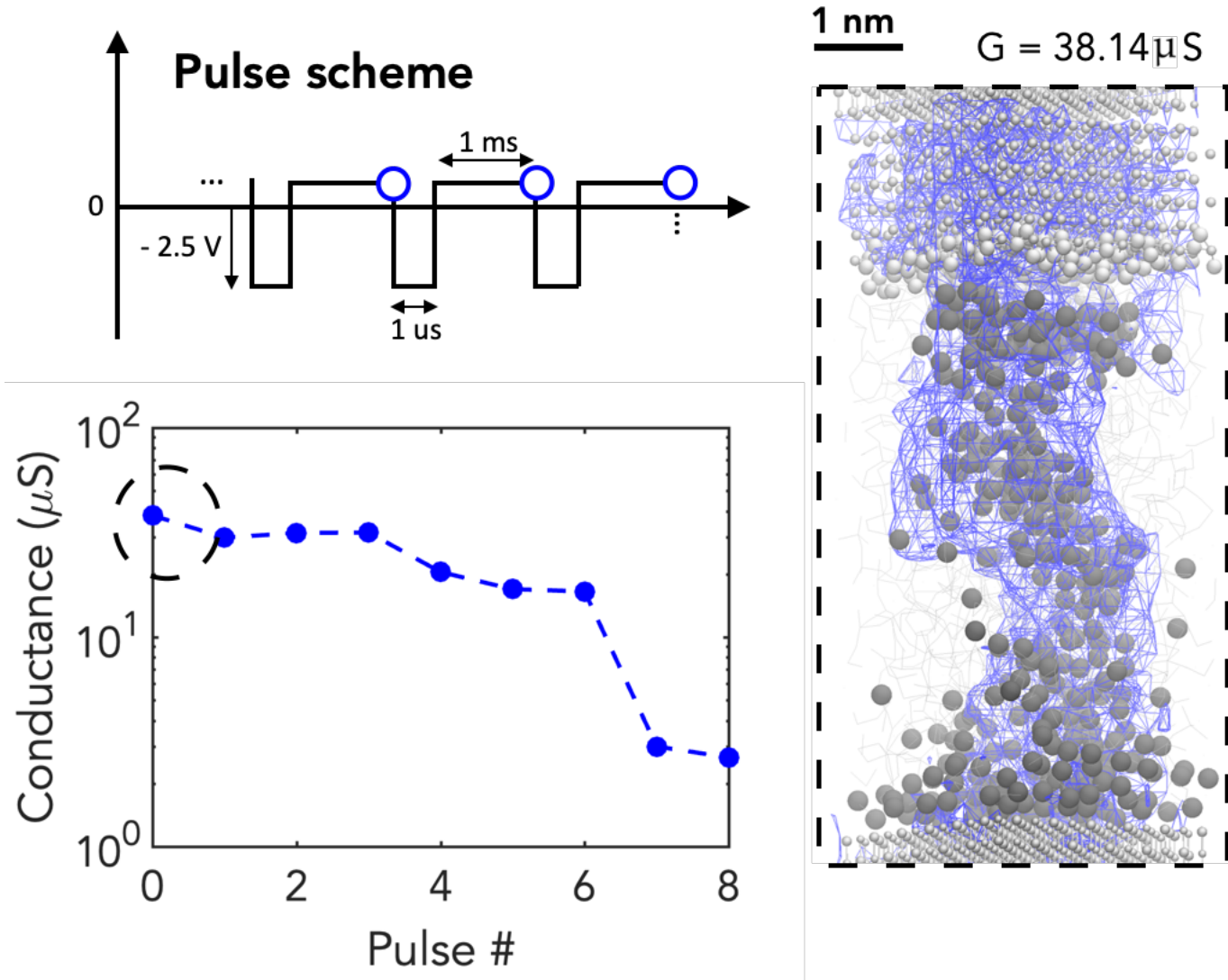
Simulation approach



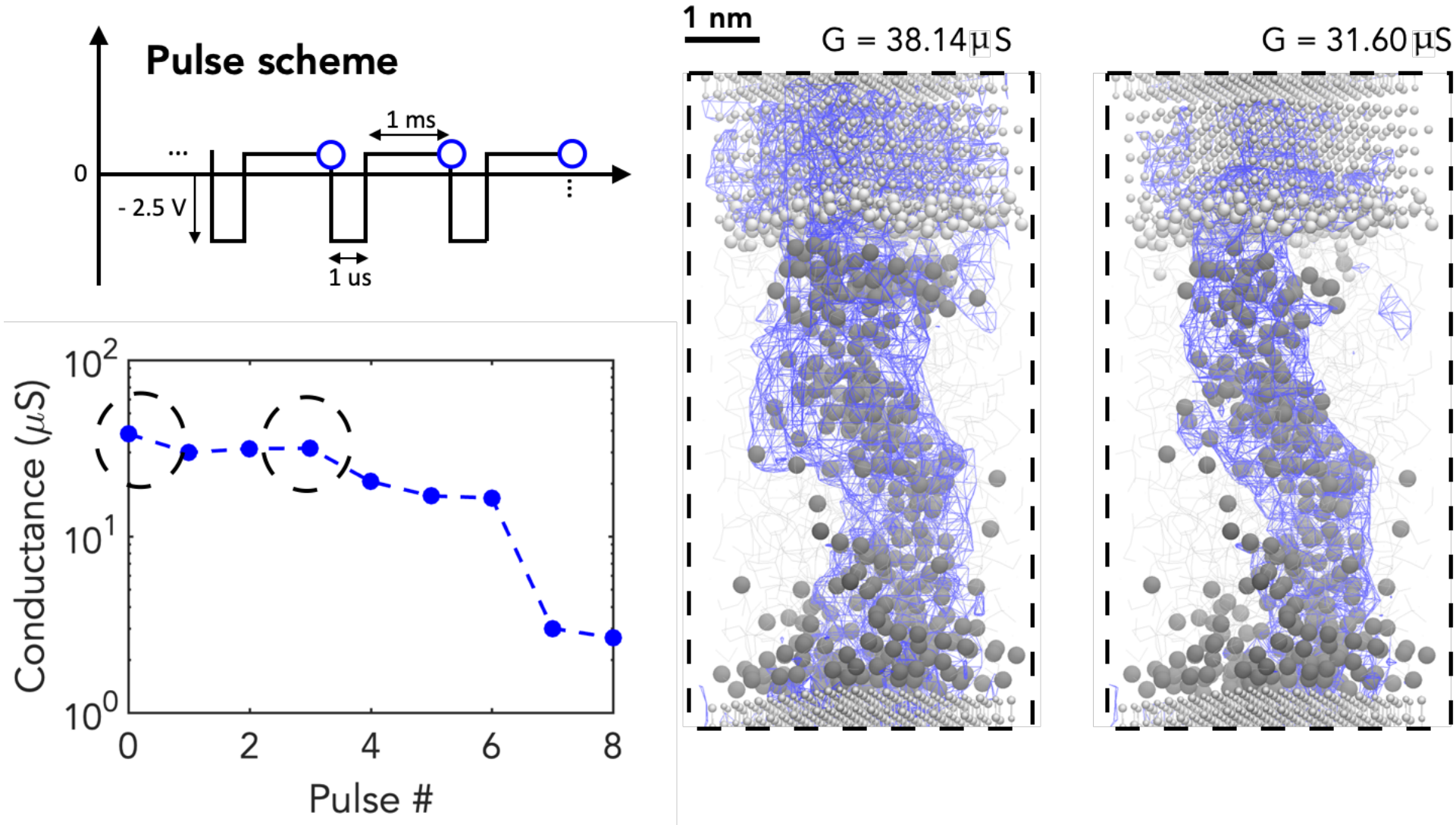
Gradual Conductance Decreases



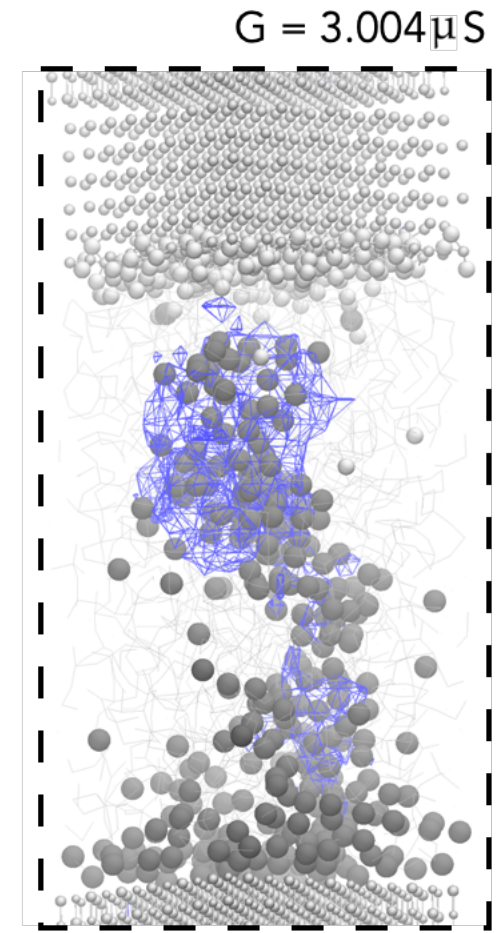
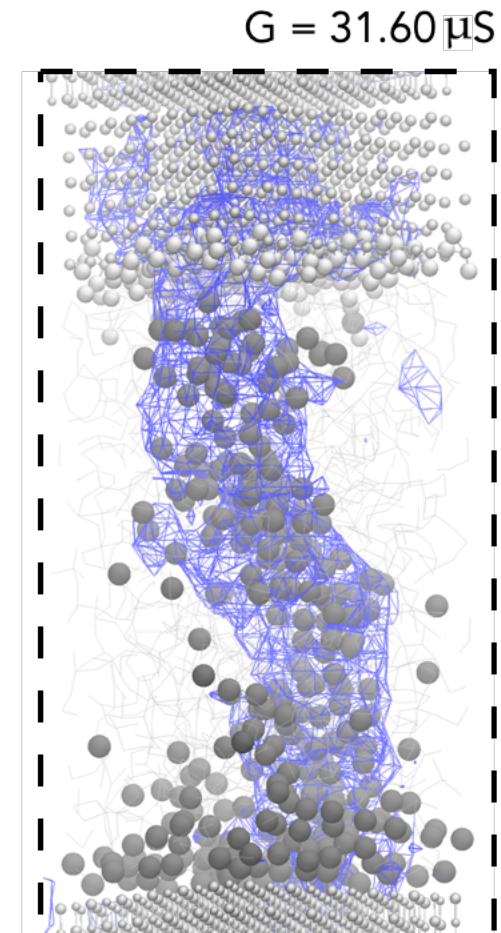
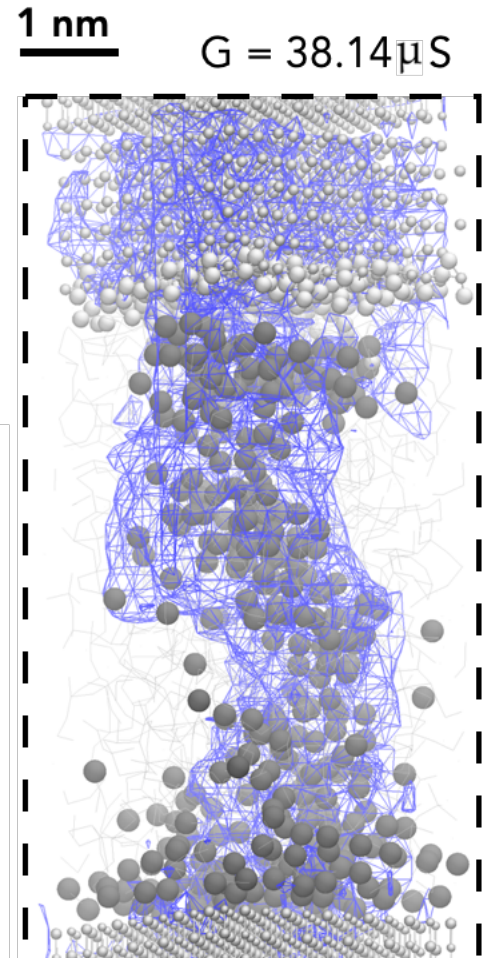
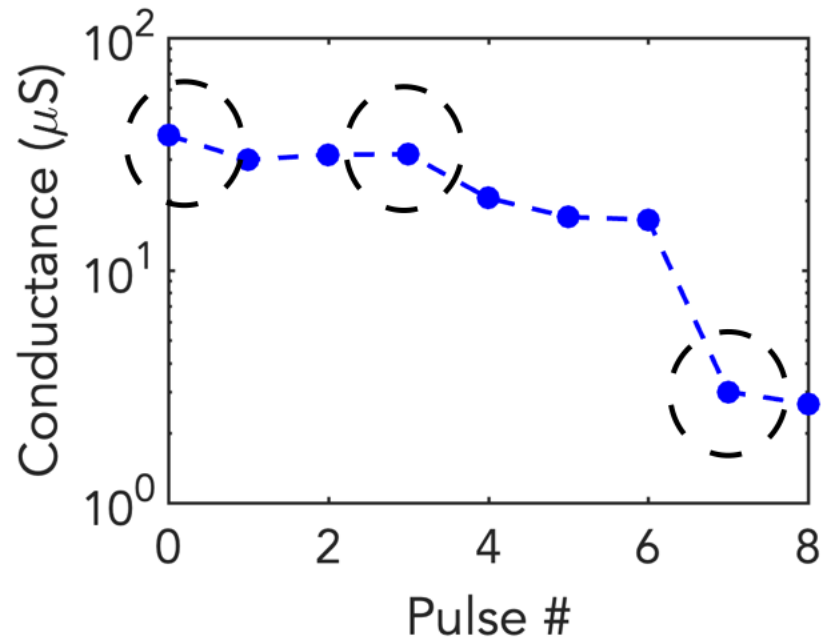
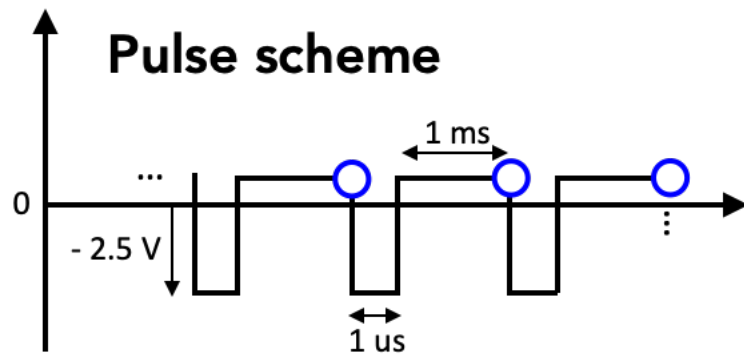
Gradual Conductance Decreases



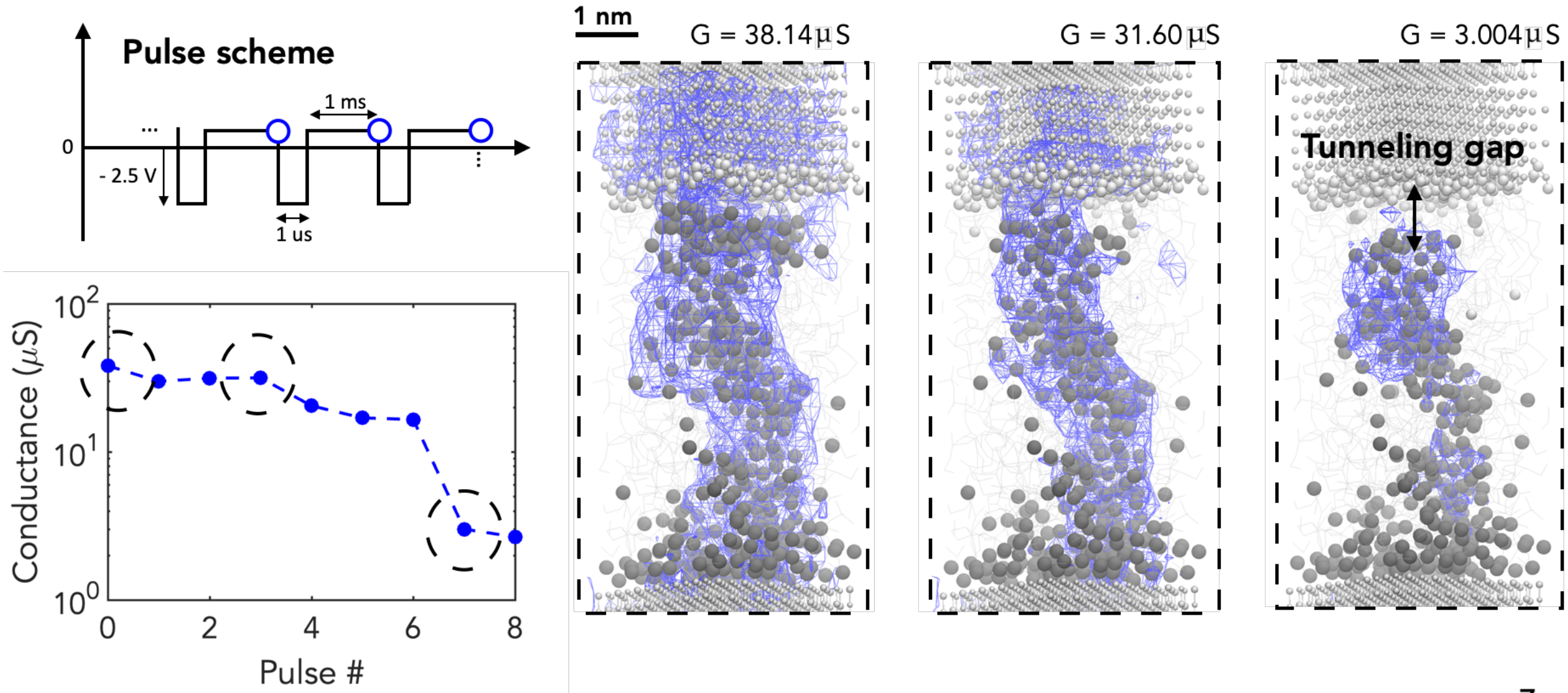
Gradual Conductance Decreases



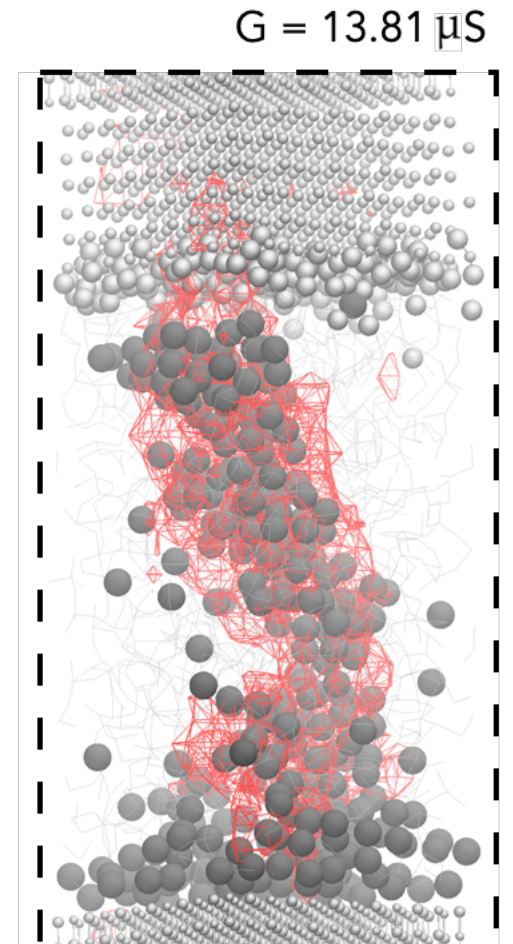
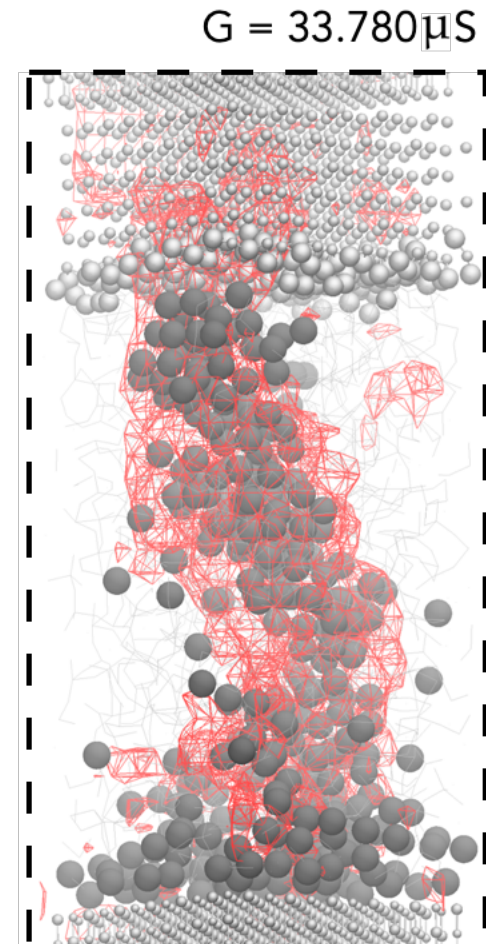
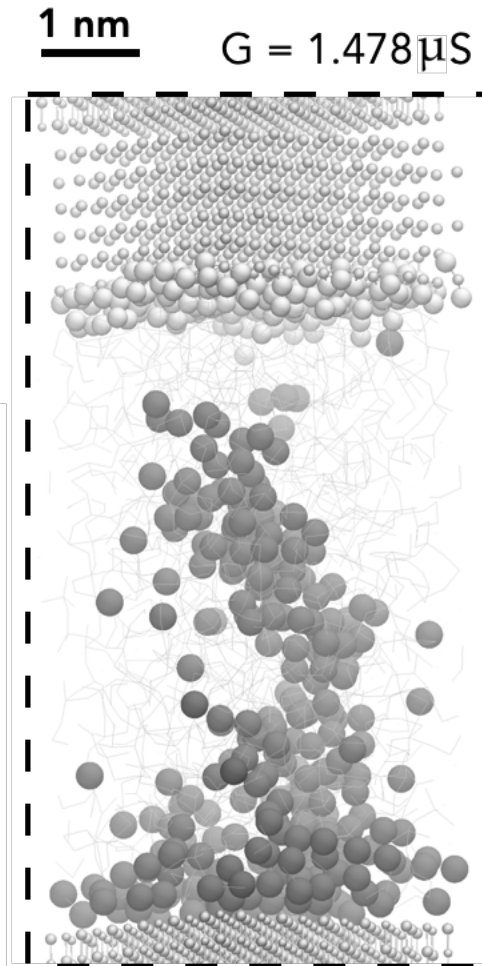
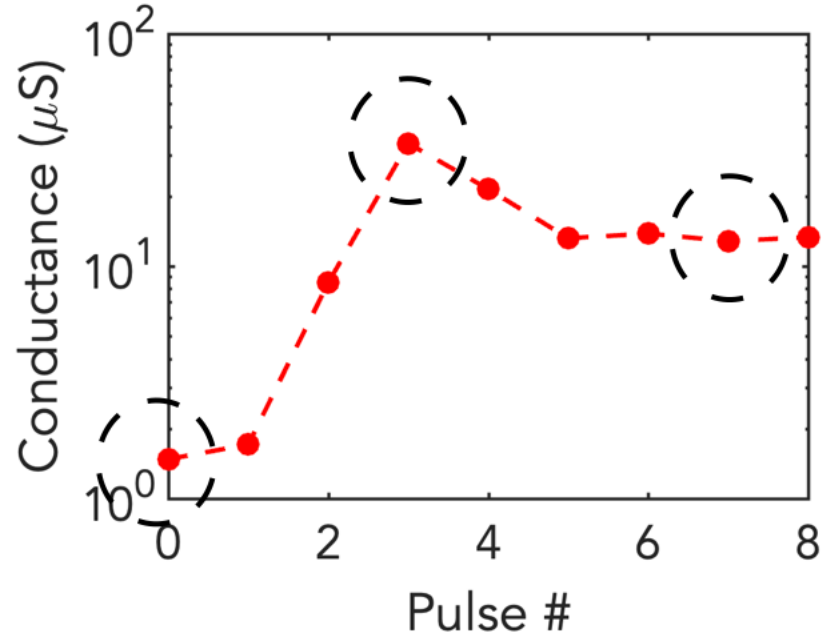
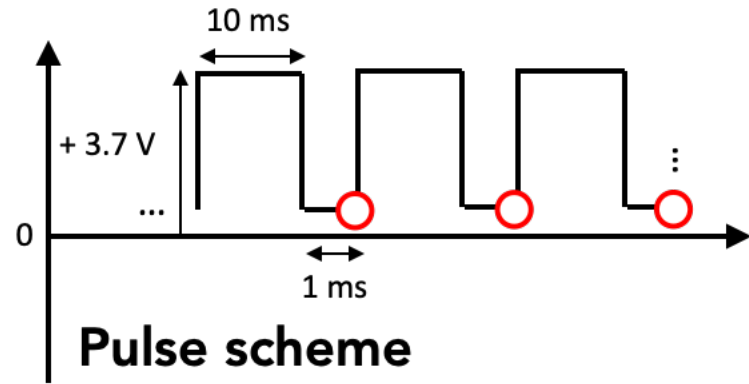
Gradual Conductance Decreases



Gradual Conductance Decreases

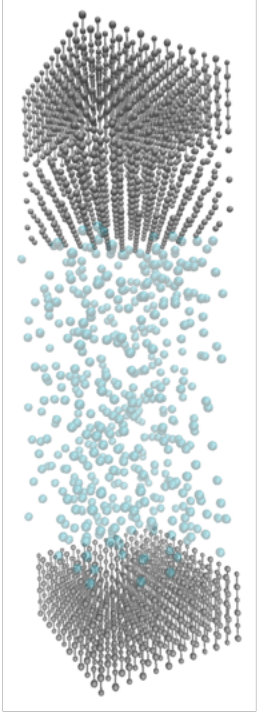


Gradual Conductance Increases



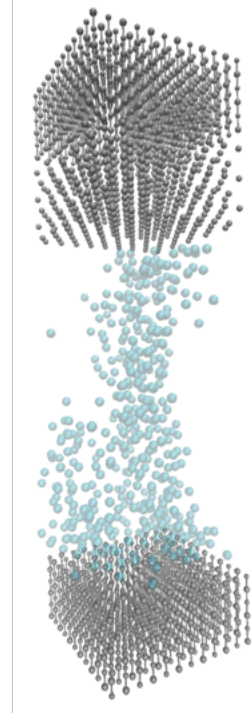
Current flow through HfO_x

Non-Filamentary



HfO_x : x = 1.512

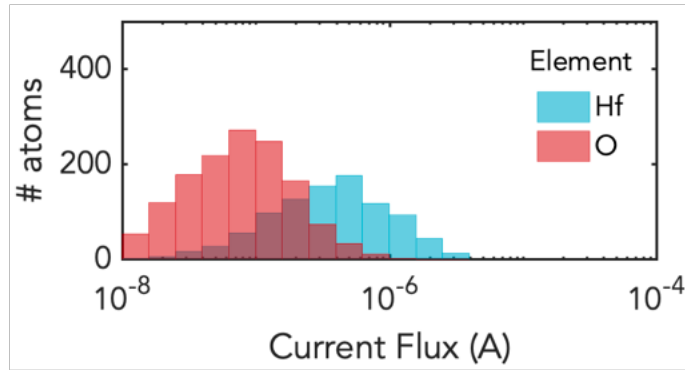
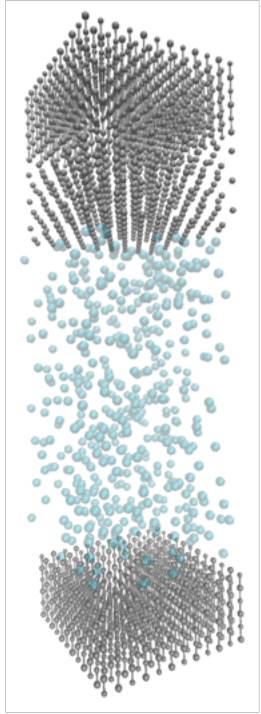
Filamentary



HfO_x : x = 1.512

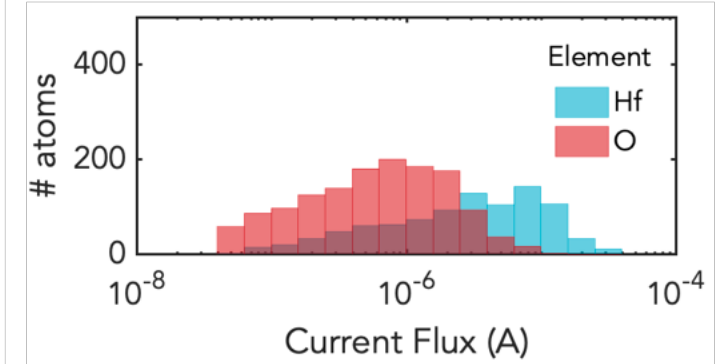
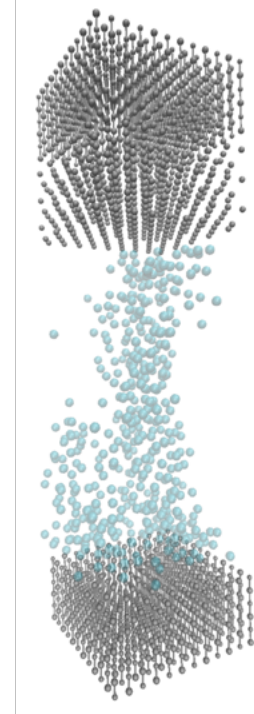
Current flow through HfO_x

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HfO_x : x = 1.512

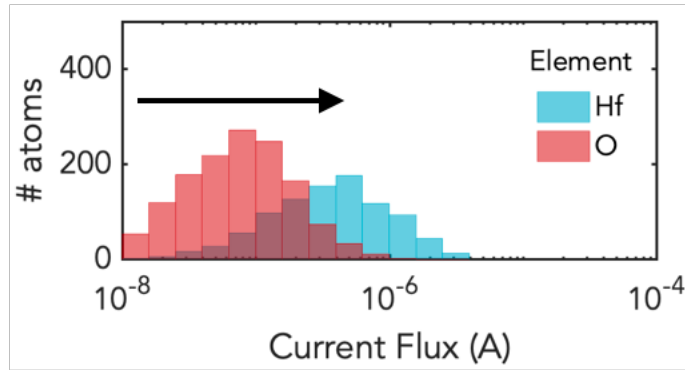
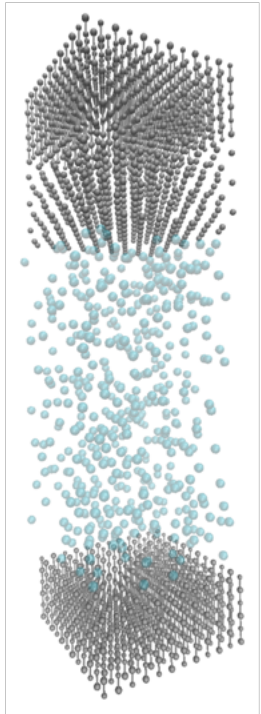
Filamentary



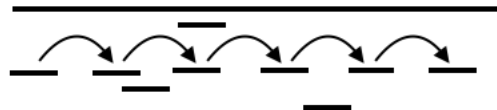
HfO_x : x = 1.512

Current flow through HfO_x

Non-Filamentary

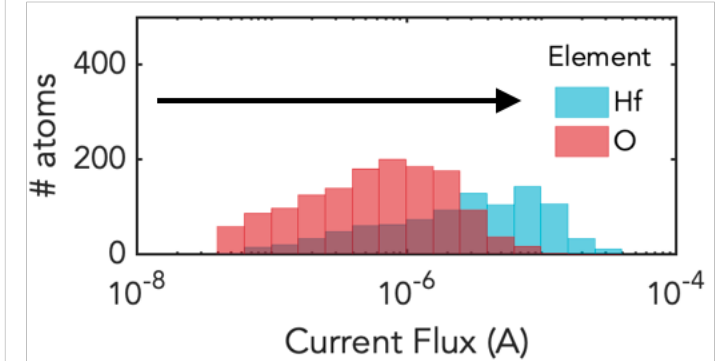
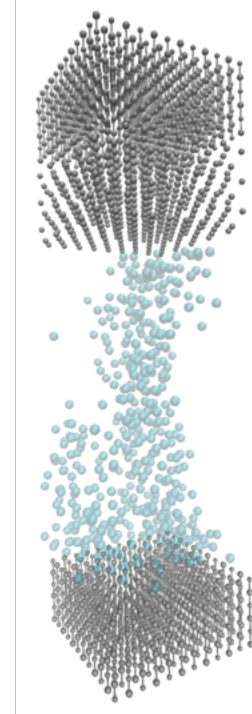


Conduction band



HfO_x : x = 1.512

Filamentary



Conduction band

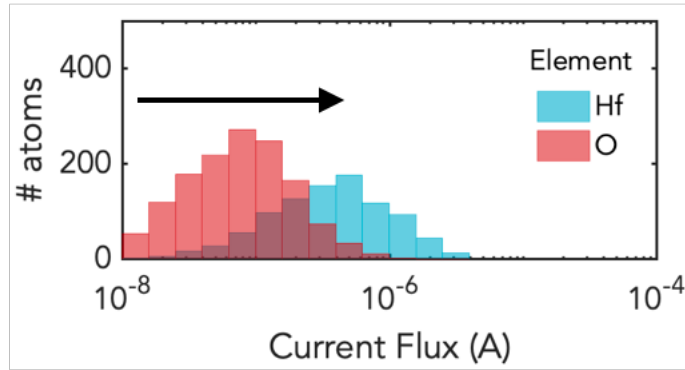
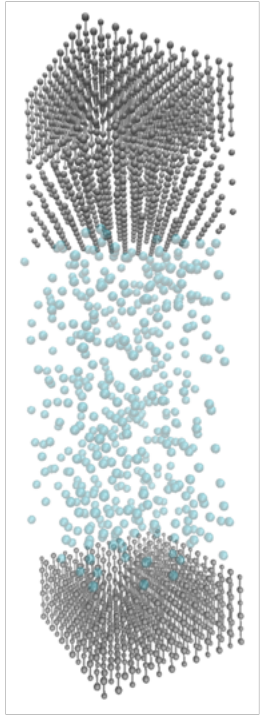


HfO_x : x = 1.512

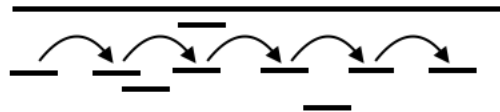
- The magnitude of current is increased in the presence of filamentary vacancy clusters

Current flow through HfOx

Non-Filamentary

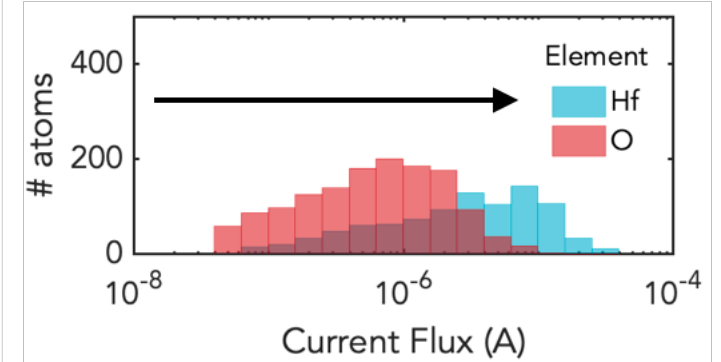
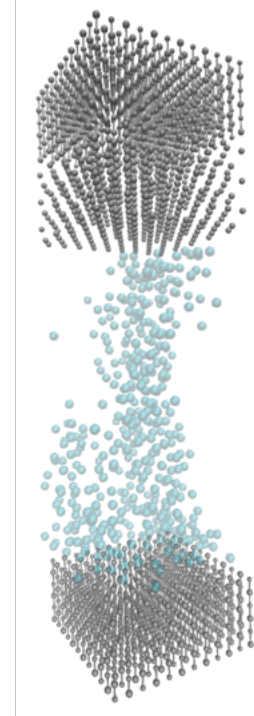


Conduction band



$\text{HfO}_x : x = 1.512$

Filamentary

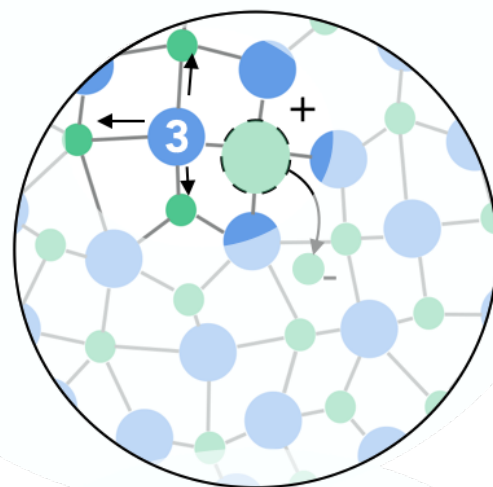
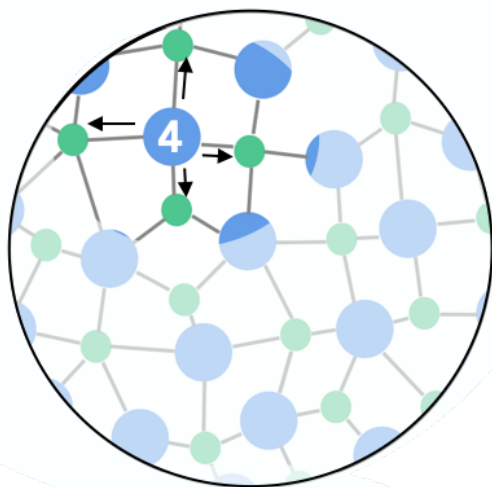
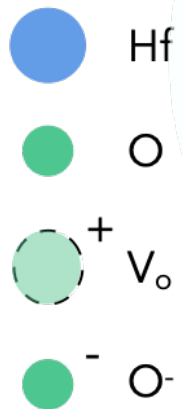


Conduction band



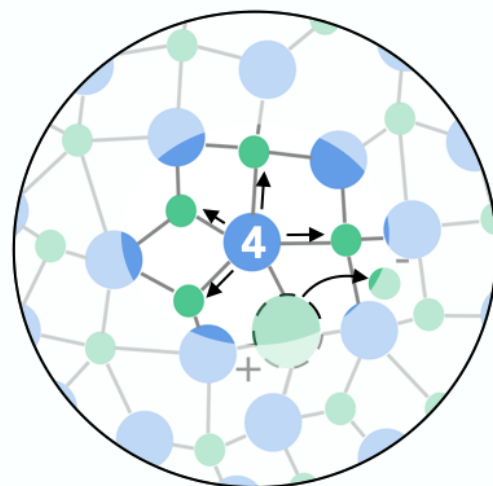
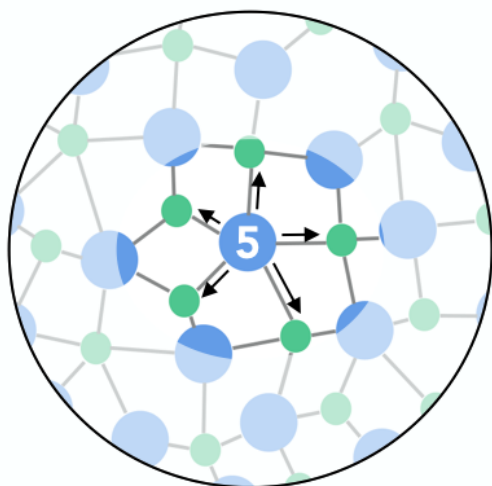
$\text{HfO}_x : x = 1.512$

- The magnitude of current is increased in the presence of filamentary vacancy clusters
- Current flows through Hf atoms



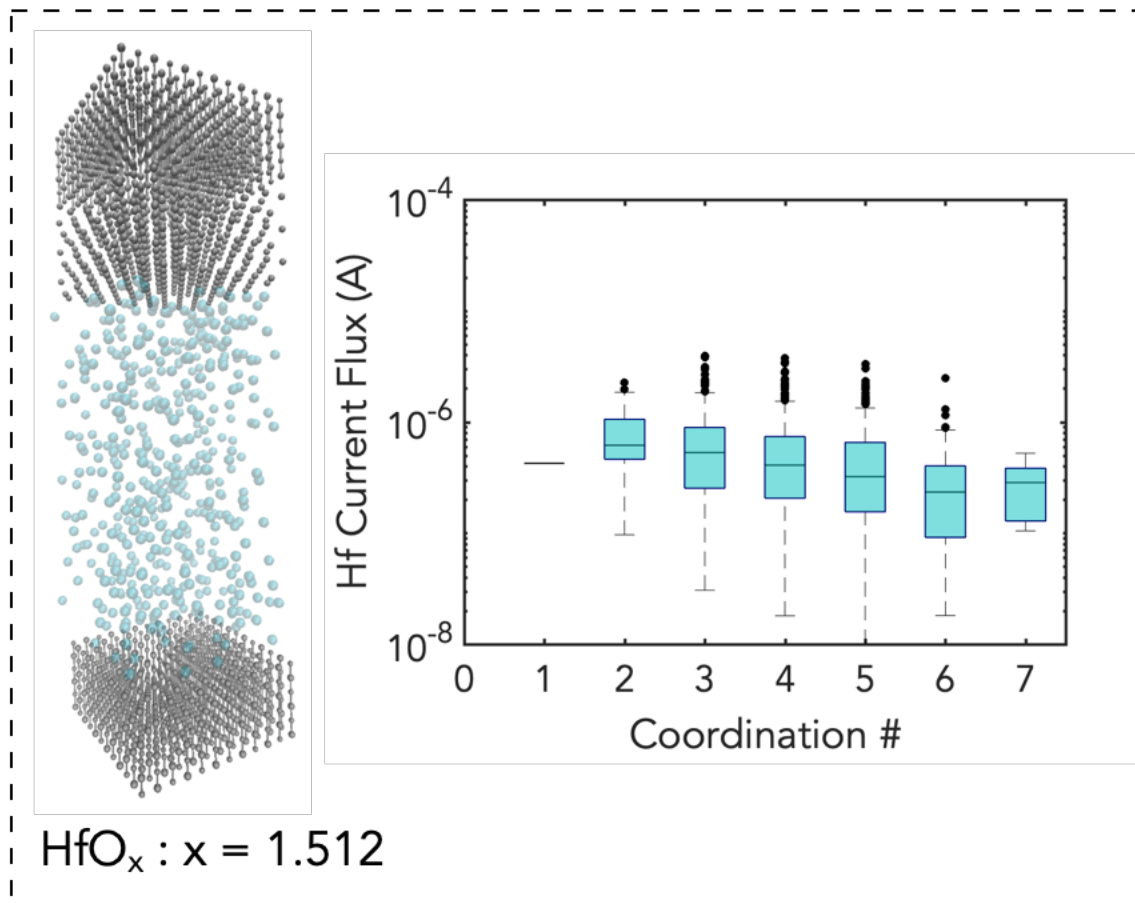
Oxygen coordination is affected by...

- Underlying atomic connectivity
- Presence of Oxygen vacancy defects

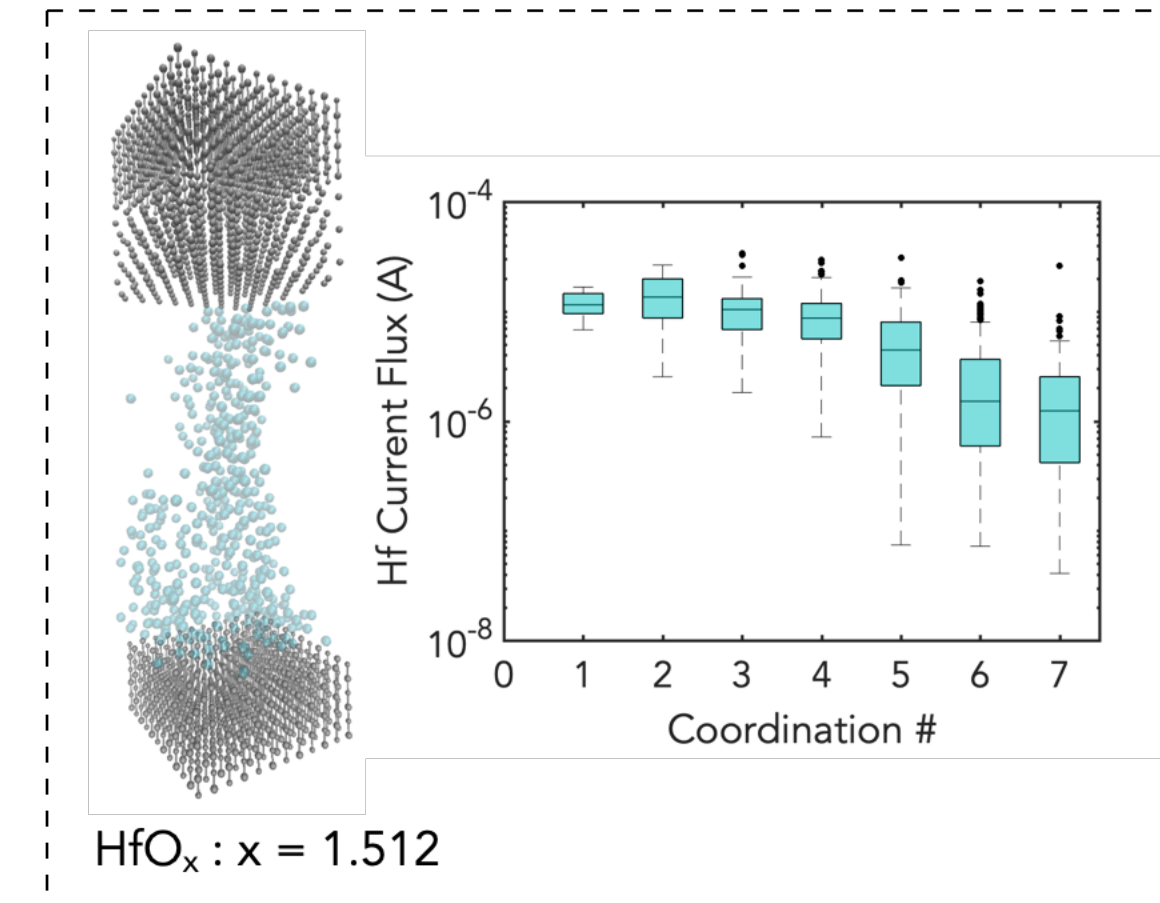


Current flow through the defective oxide

Non-Filamentary

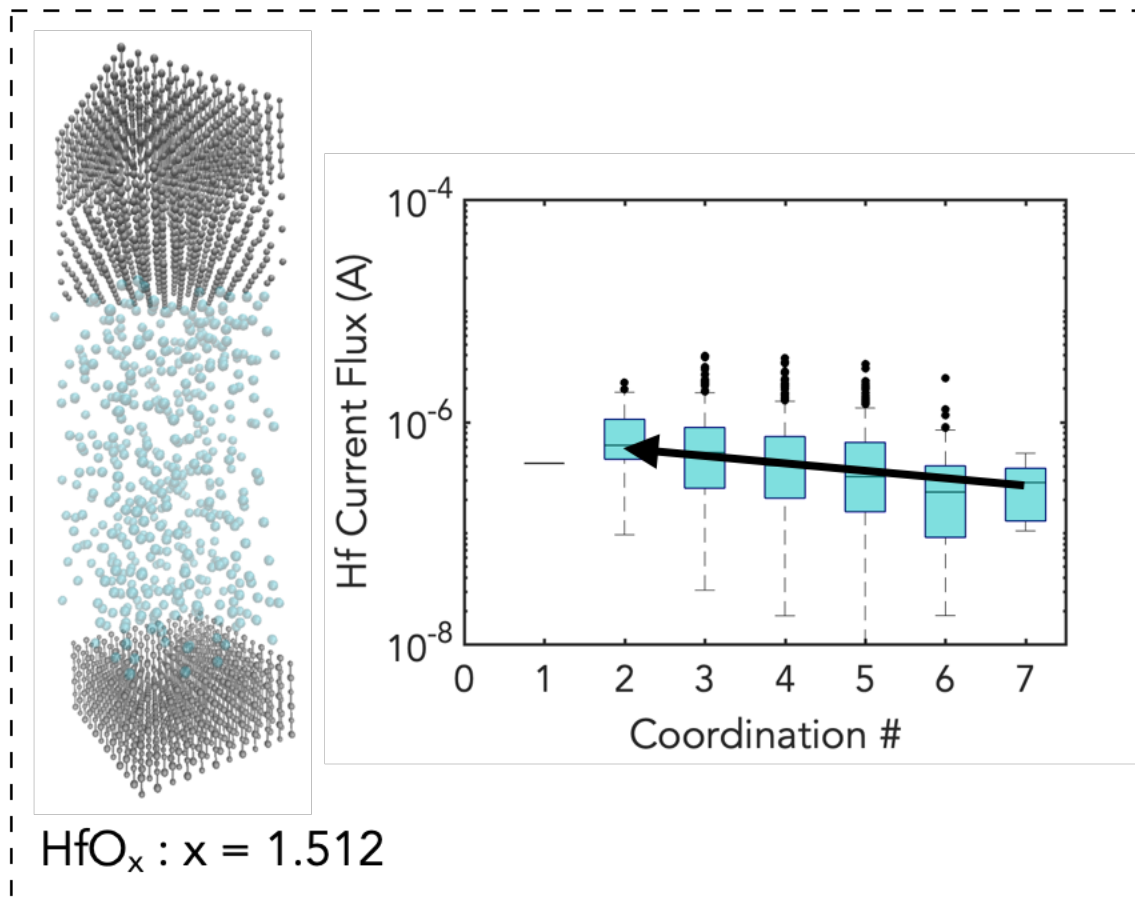


Filamentary

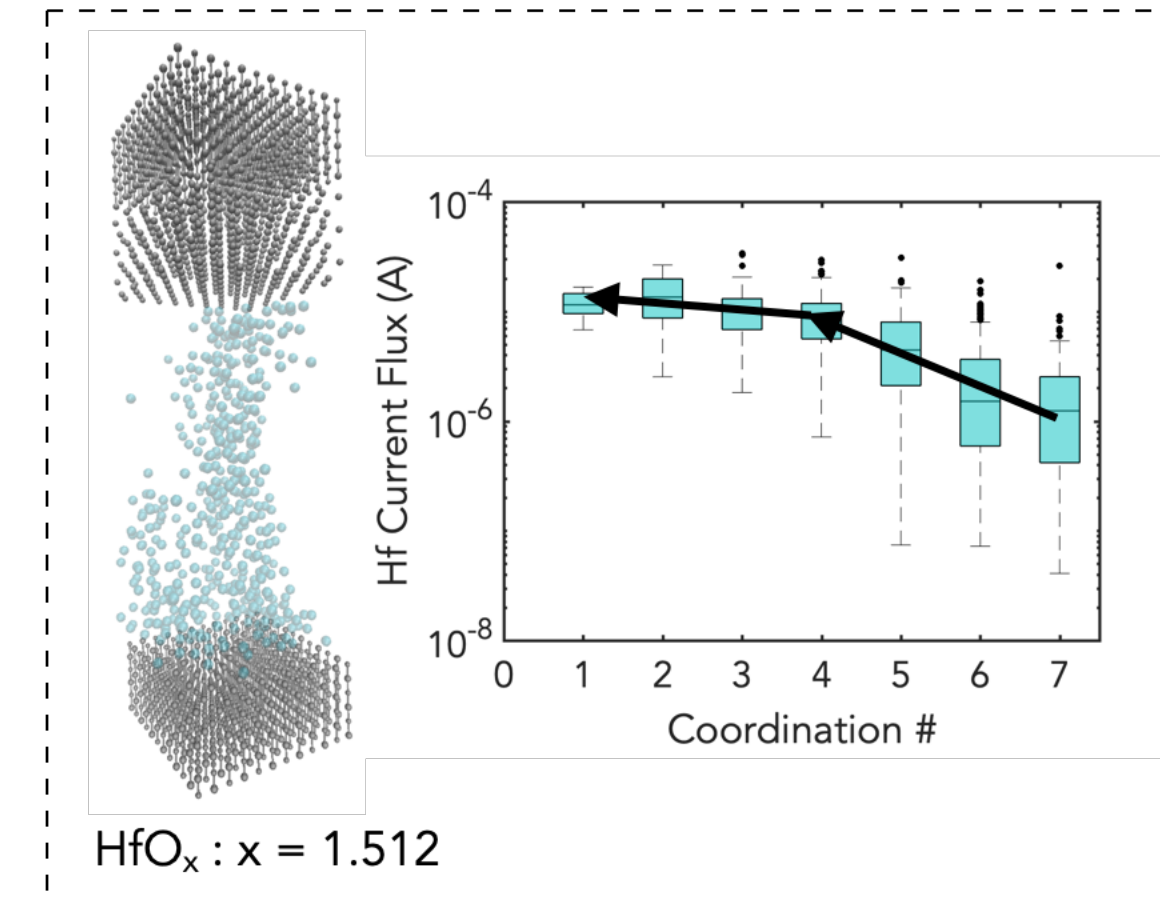


Current flow through the defective oxide

Non-Filamentary

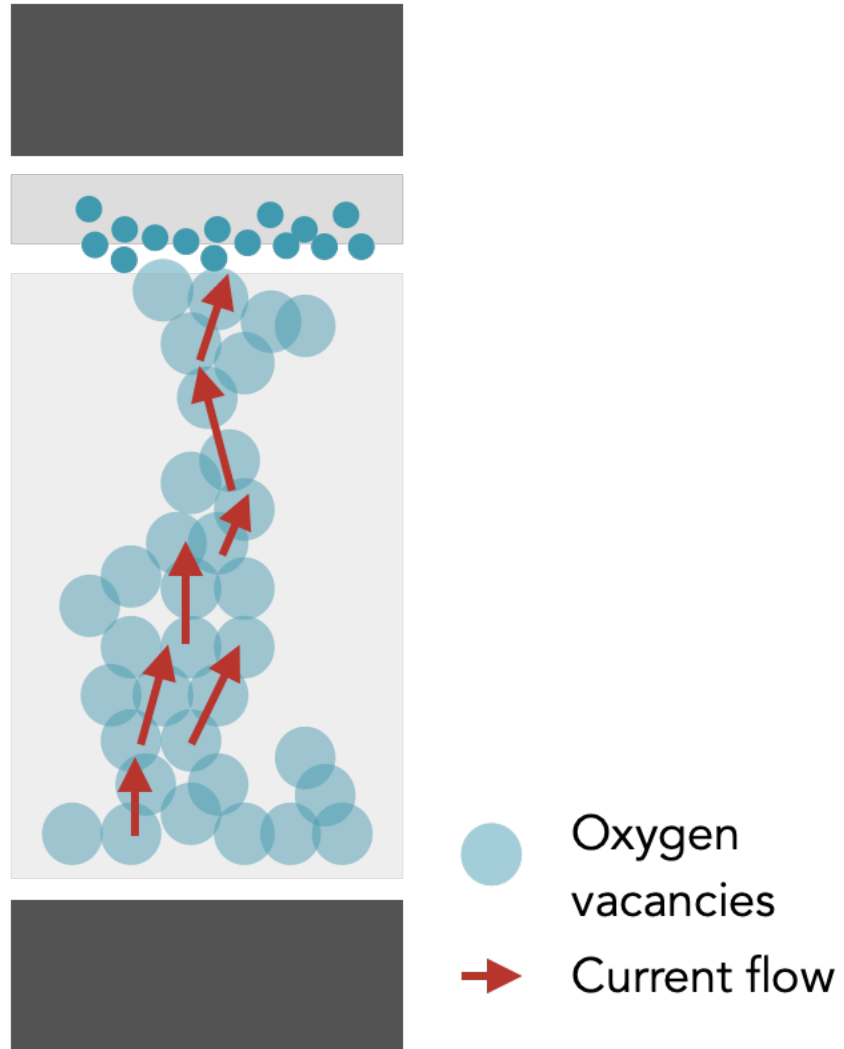


Filamentary



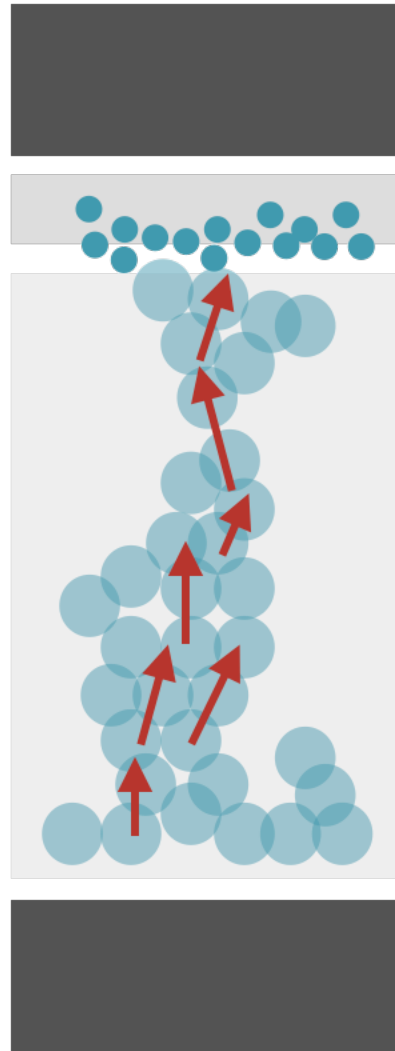
Summary

Some atoms direct **more** of the electronic current

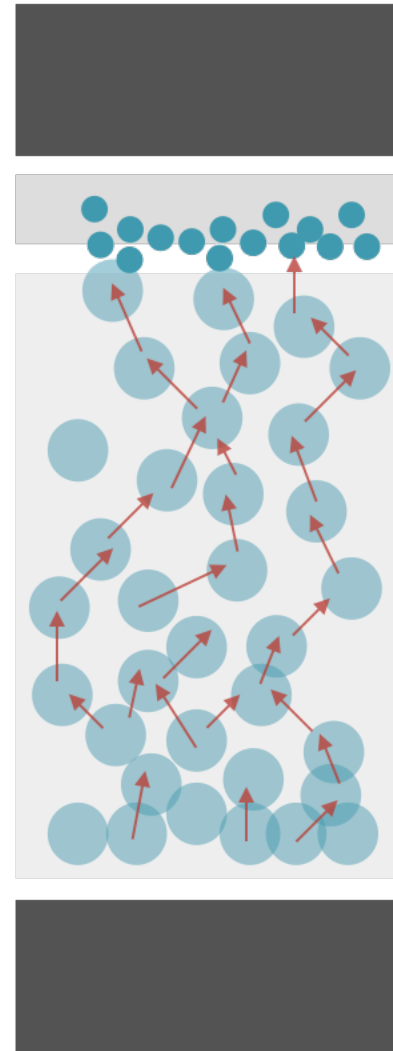


Summary

Some atoms direct **more** of the electronic current



Individual atoms direct **less** of the electronic current



● Oxygen vacancies
➔ Current flow

Outlook: Methods to improve analog operation

Chemical/compositional

- Adding dopants/nucleation sites
- Engineered bilayers with interface-type switching

Thermal

- Thermal Enhancement Layers
- Optical pulses
- Operating at higher temperatures

Outlook: Methods to improve analog operation

Chemical/compositional

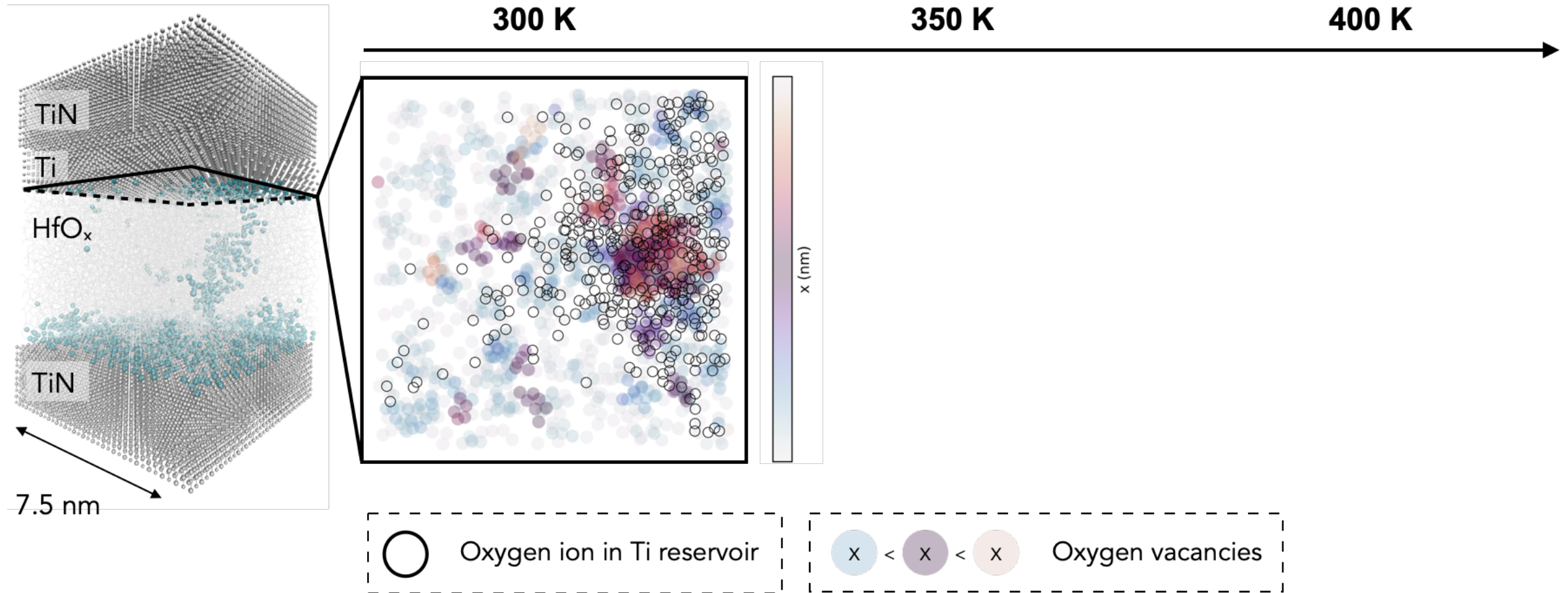
- Adding dopants/nucleation sites
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Thermal

- Thermal Enhancement Layers
- Optical pulses
- Operating at higher temperatures

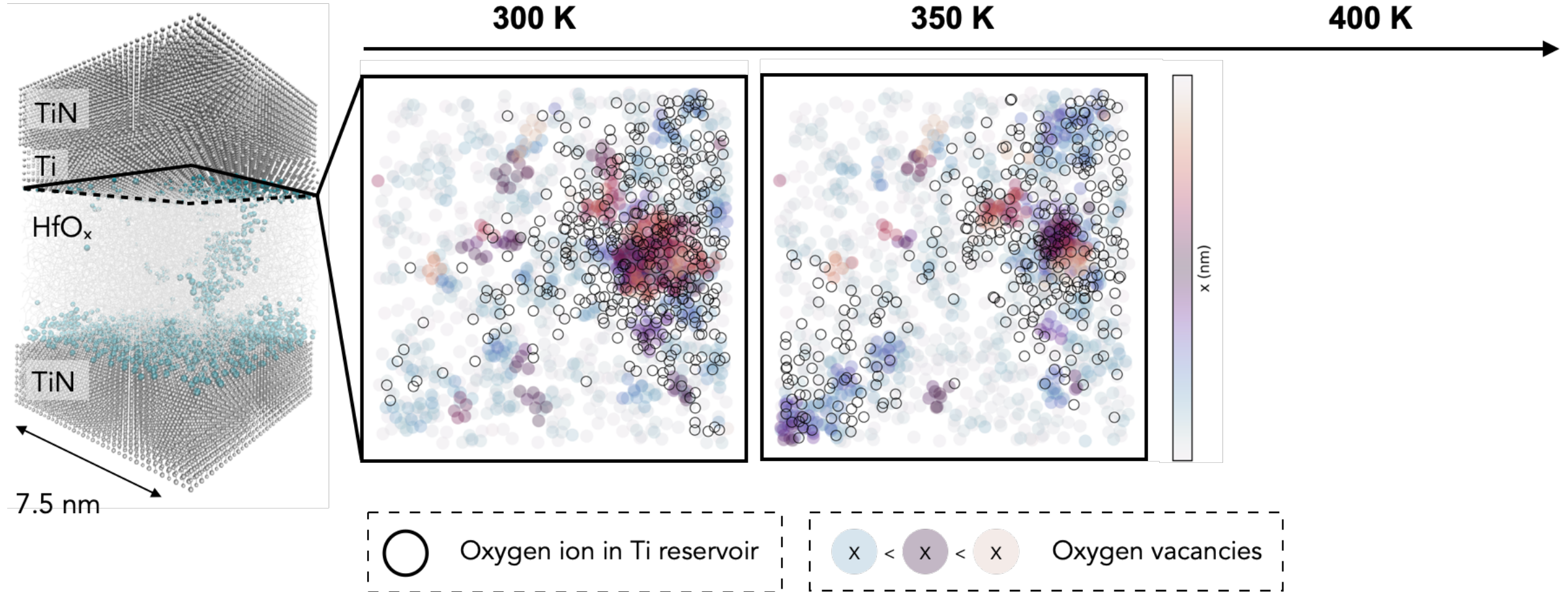
Outlook: Thermal engineering

Increasing electroforming temperature at fixed $V_{\text{FORM}} = 6.0 \text{ V}$

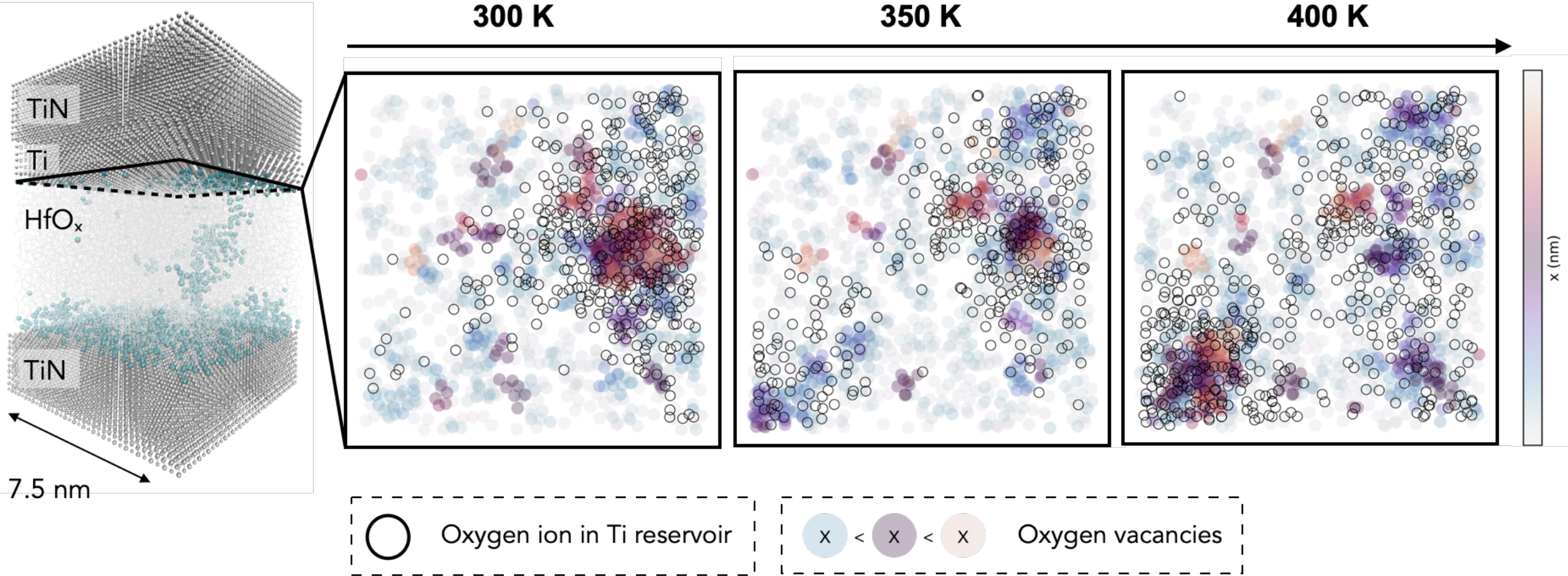


Outlook: Thermal engineering

Increasing electroforming temperature at fixed $V_{\text{FORM}} = 6.0 \text{ V}$

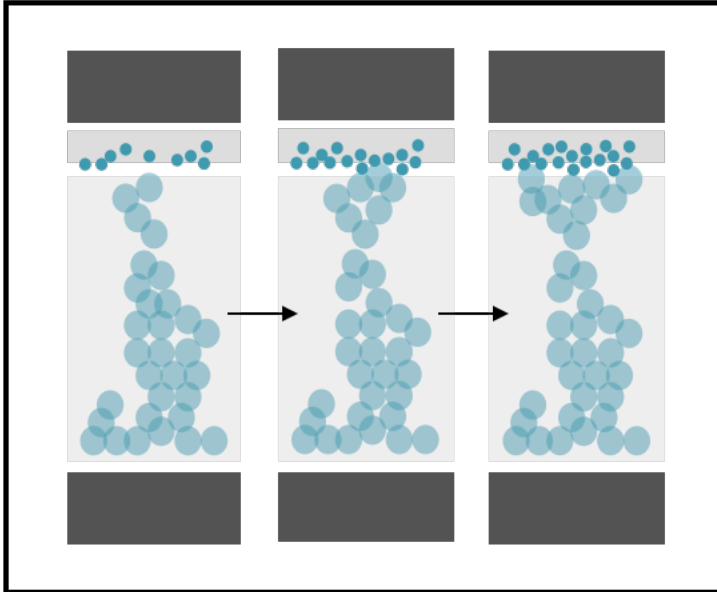


Outlook: Thermal engineering

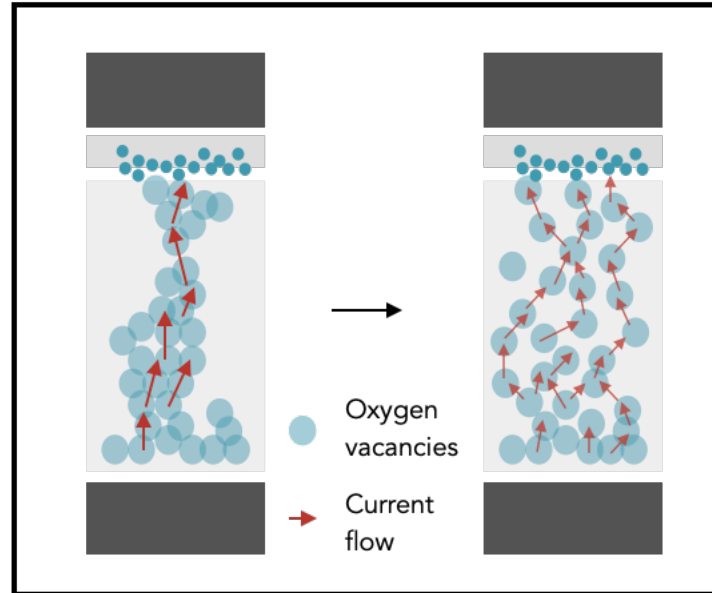


Summary and Acknowledgements

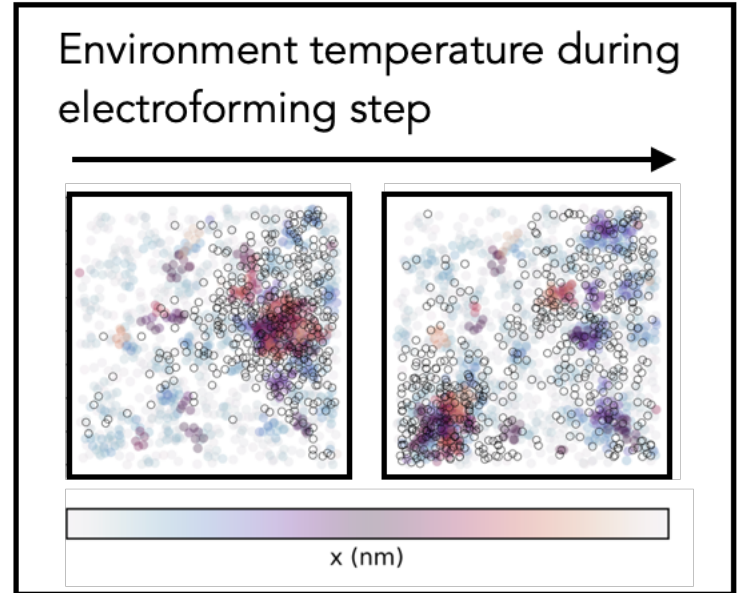
Origin of non-linear conductance updates



Coordination-dependence of current flow



Methods to achieve more uniformly defective oxides



Discussions, moral support:

Marko Mladenović

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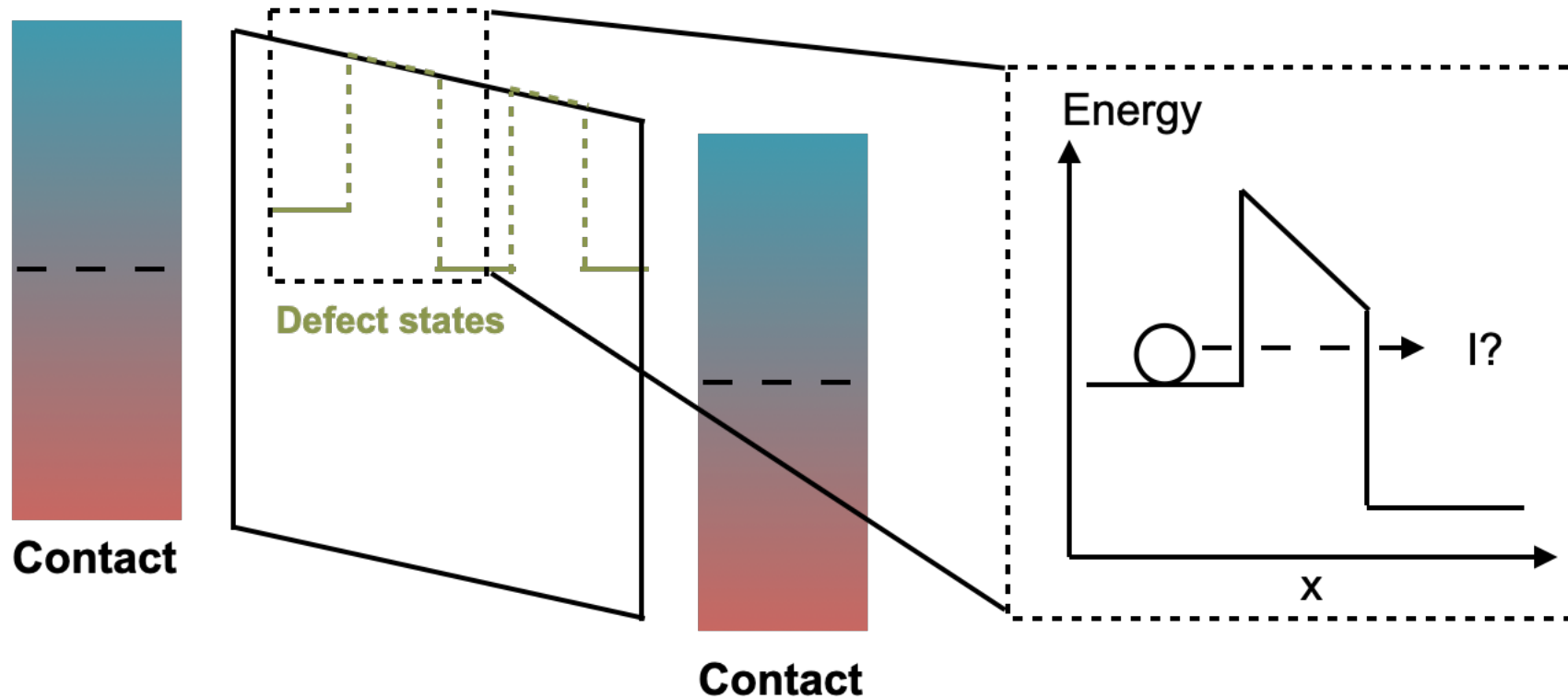


Swiss National
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Mechanisms of Current Flow: Tunneling



$$T(E) = \exp\left(-\int \text{Im}(k(E)dx)\right) \xrightarrow{E = \frac{\hbar^2 k^2}{2m}} T(E) = \exp\left(-\frac{2m_e}{\hbar} \int \sqrt{E} dx\right)$$

Mechanisms of Current Flow: Tunneling

